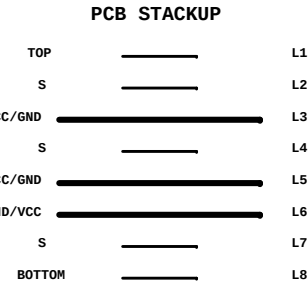


Project code: 91.4CQ01.001
PCB P/N : 48.4CQ01.0SB
REVISION : 08274-1



DIS			
		Wistron Corporation 21F, 88, Sec.1, Hsin Ta Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
BLOCK DIAGRAM			
Size Custom	Document Number	JM41 Discrete	Rev -2
Date:	Tuesday, April 28, 2009	Sheet 1 of	48

ICH9M Functional Strap Definitions

ICH9 EDS 642879 Rev.1.5 page 92

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIE Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers: offset 224h). This signal has weak internal pull-down
HDA_SYNC	PCIE config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#/GPI053	PCIE config2 bit2, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPI020	Reserved	This signal should not be pulled high.
GNT1#/GPI051	ESI Strap (Server Only) Rising Edge of PWROK	ESI compatible mode is for server platforms only. This signal should not be pulled low for desttop and mobile.
GNT3#/GPI055	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#: SPI_CS1#/GPI058	Boot BIOS Destination Selection 0:1. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
SPI_MOSI	Integrated TPM Enable, Rising Edge of CLPWROK	Sample low: the Integrated TPM will be disabled. Sample high: the MCH TPM enable strap is sampled low and the TPM Disable bit is clear, the Integrated TPM will be enable.
GPI049	DMI Termination Voltage, Rising Edge of PWROK.	The signal is required to be low for desktop applications and required to be high for mobile applications.
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH9 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPI033/HDA_DOCK_EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be enabled in manufacturing environments using an external pull-up resistor.

ICH9M Integrated Pull-up and Pull-down Resistors

ICH9 EDS 642879 Rev.1.5

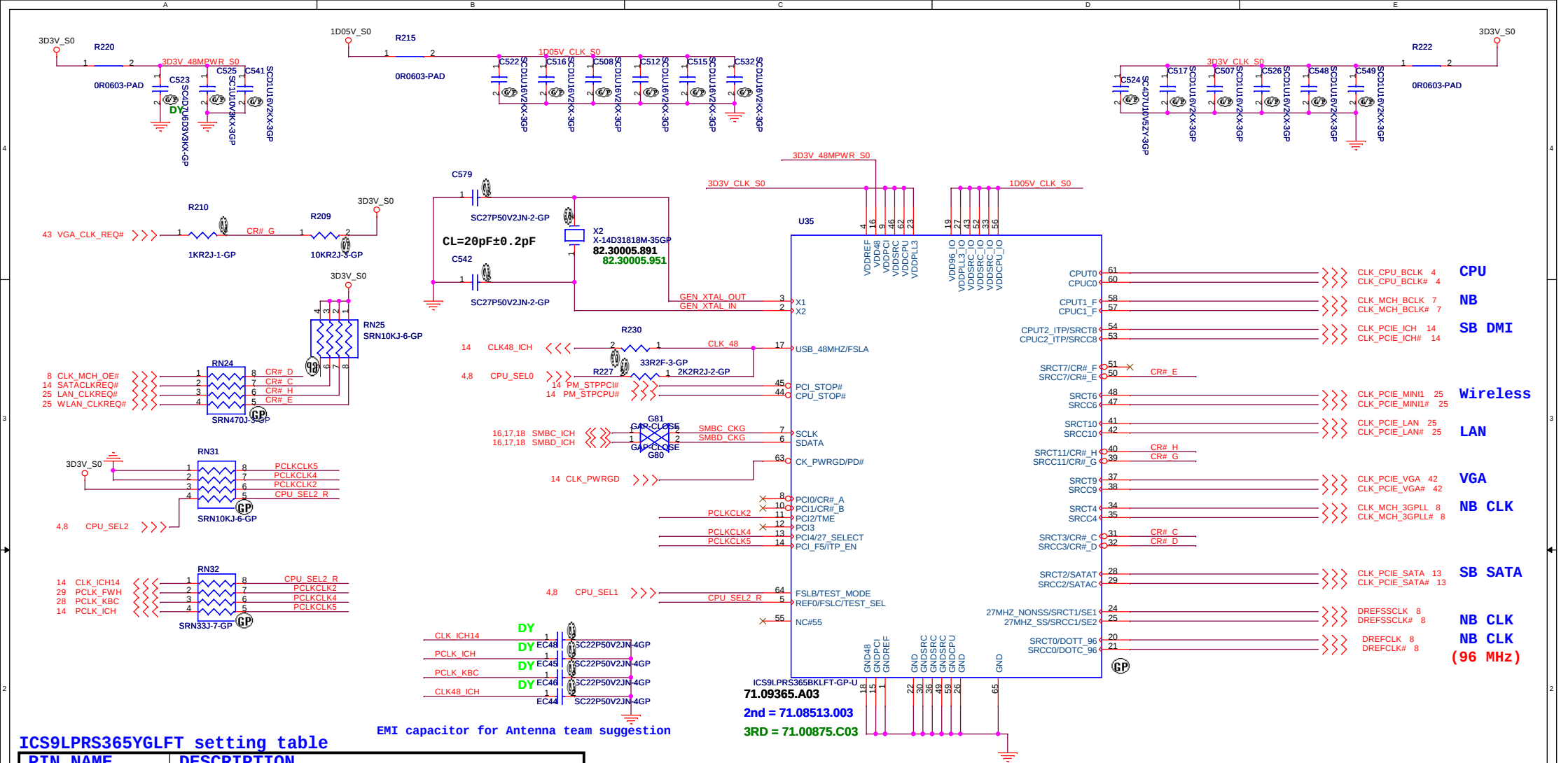
SIGNAL	Resistor Type/Value
CL_CLK[1:0]	PULL-UP 20K
CL_DATA[1:0]	PULL-UP 20K
CL_RST0#	PULL-UP 20K
DPRSLPVR/GPIO16	PULL-DOWN 20K
ENERGY_DETECT	PULL-UP 20K
HDA_BIT_CLK	PULL-DOWN 20K
HDA_DOCK_EN#/GPIO33	PULL-UP 20K
HDA_RST#	PULL-DOWN 20K
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GLAN_DOCK#	The pull-up or pull-down active when configured for native GLAN_DOCK# functionality and determined by LAN controller
GNT[3:0]#/GPIO[55, 53, 51]	PULL-UP 20K
GPI0[20]	PULL-DOWN 20K
GPI0[49]	PULL-UP 20K
LDA[3:0]#/FWH[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 20K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPI023	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#/GPIO58/CLGPI06	PULL-UP 20K
SPI_MOSI	PULL-DOWN 20K
SPI_MISO	PULL-UP 20K
SPKR	PULL-DOWN 20K
TACH_[3:0]	PULL-UP 20K
TP[3]	PULL-UP 20K
USB[11:0][P,N]	PULL-DOWN 15K

Cantiga chipset and ICH9M I/O controller Hub strapping configuration

Montevina Platform Design guide 22339 0.5 page 218

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	000 = FSB1067 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3] CFG8 CFG[15:14] CFG[18:17]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG6	iTPM Host Interface	0= The iTPM Host Interface is enabled(Note2) 1=The iTPM Host Interface is disalbed(default)
CFG7	Intel Management engine Crypto strap	0 = Transport Layer Security (TLS) cipher suite with no confidentiality 1 = TLS cipher suite with confidentiality (default)
CFG9	PCIE Graphics Lane	0 = Reverse Lanes,15->0,14->1 ect.. 1= Normal operation(Default):Lane Numbered in order
CFG10	PCIE Loopback enable	0 = Enable (Note 3) 1= Disabled (default)
CFG[13:12]	XOR/ALL	00 = Reserve 10 = XOR mode Enabled 01 = ALLZ mode Enabled (Note 3) 11 = Disabled (default)
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG19	DMI Lane Reversal	0 = Normal operation(Default): Lane Numbered in Order 1 = Reverse Lanes x4 mode[MCH -> ICH]:(3->0,2->1,1->2and0->3) DMI x2 mode[MCH -> ICH]:(3->0,2->1)
CFG20	Digital Display Port (SDVO/DP/iHDMI) Concurrent with PCIE	0 = Only Digital Display Port or PCIE is operational (Default) 1 = Digital display Port and PCie are operating simulatanuously via the PEG port
SDVO_CTRLDATA	SDVO Present	0 =No SDVO Card Present (Default) 1 = SDVO Card Present
L_DDC_DATA	Local Flat Panel (LFP) Present	0 = LFP Disabled (Default) 1= LFP Card Present; PCIE disabled

NOTE:
1. All strap signals are sampled with respect to the leading edge of the (G)MCH Power OK (PWROK) signal.
2. iTPM can be disabled by a 'Soft-Strap' option in the Flash-decriptor section of the Firmware. This 'Soft-Strap' is activated only after enabling iTPM via CFG6.
Only one of the CFG10/CFG12/CFG13 straps can be enabled at any time.



ICS9LPRS365YGLFT setting table

PIN	NAME	DESCRIPTION
PCI0/CR#_A		Byte 5, bit 7 0 = PCI0 enabled (default) 1 = CR# A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR# A controls SRC0 pair (default), 1 = CR#_A controls SRC2 pair
PCI1/CR#_B		Byte 5, bit 5 0 = PCI1 enabled (default) 1 = CR# B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 6 0 = CR# B controls SRC0 pair (default) 1 = CR#_B controls SRC4 pair
PCI2/TME		0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI3		
PCI4/27M_SEL		0 = Pin17 as SRC-1, Pin18 as SRC-1#, Pin13 as D0Y96, Pin14 as D0Y96# 1 = Pin17 as 27MHz, Pin 18 as 27MHz_SS, Pin13 as SRC-0, Pin14 as SRC-0#
PCI_F5/ITP_EN		0 = SRC8/SRC8# 1 = ITP/ITP#
SRCT3/CR#_C		Byte 5, bit 3 0 = SRC3 enabled (default) 1 = CR# C enabled. Byte 5, bit 2 controls whether CR#_C controls SRC0 or SRC2 pair Byte 5, bit 2 0 = CR# C controls SRC0 pair (default), 1 = CR#_C controls SRC2 pair

EMI capacitor for Antenna team suggestion

PIN	NAME	DESCRIPTION
SRCC3/CR#_D		Byte 5, bit 1 0 = SRC3 enabled (default) 1 = CR# D enabled. Byte 5, bit 0 controls whether CR#_D controls SRC1 or SRC4 pair Byte 5, bit 0 0 = CR#_D controls SRC1 pair (default) 1 = CR#_D controls SRC4 pair
SRCC7/CR#_E		Byte 6, bit 7 0 = SRC7 enabled (default) 1 = CR#_F controls SRC6
SRCT7/CR#_F		Byte 6, bit 6 0 = SRC7 enabled (default) 1 = CR#_F controls SRC8
SRCC11/CR#_G		Byte 6, bit 5 0 = SRC11# enabled (default) 1 = CR#_G controls SRC9
SRCT11/CR#_H		Byte 6, bit 4 0 = SRC11 enabled (default) 1 = CR#_H controls SRC10

SEL2 FSC	SEL1 FSB	SEL0 FSA	CPU	FSB
1	0	1	100M	X
0	0	1	133M	533M
0	1	1	166M	667M
0	1	0	200M	800M
0	0	0	266M	1067M

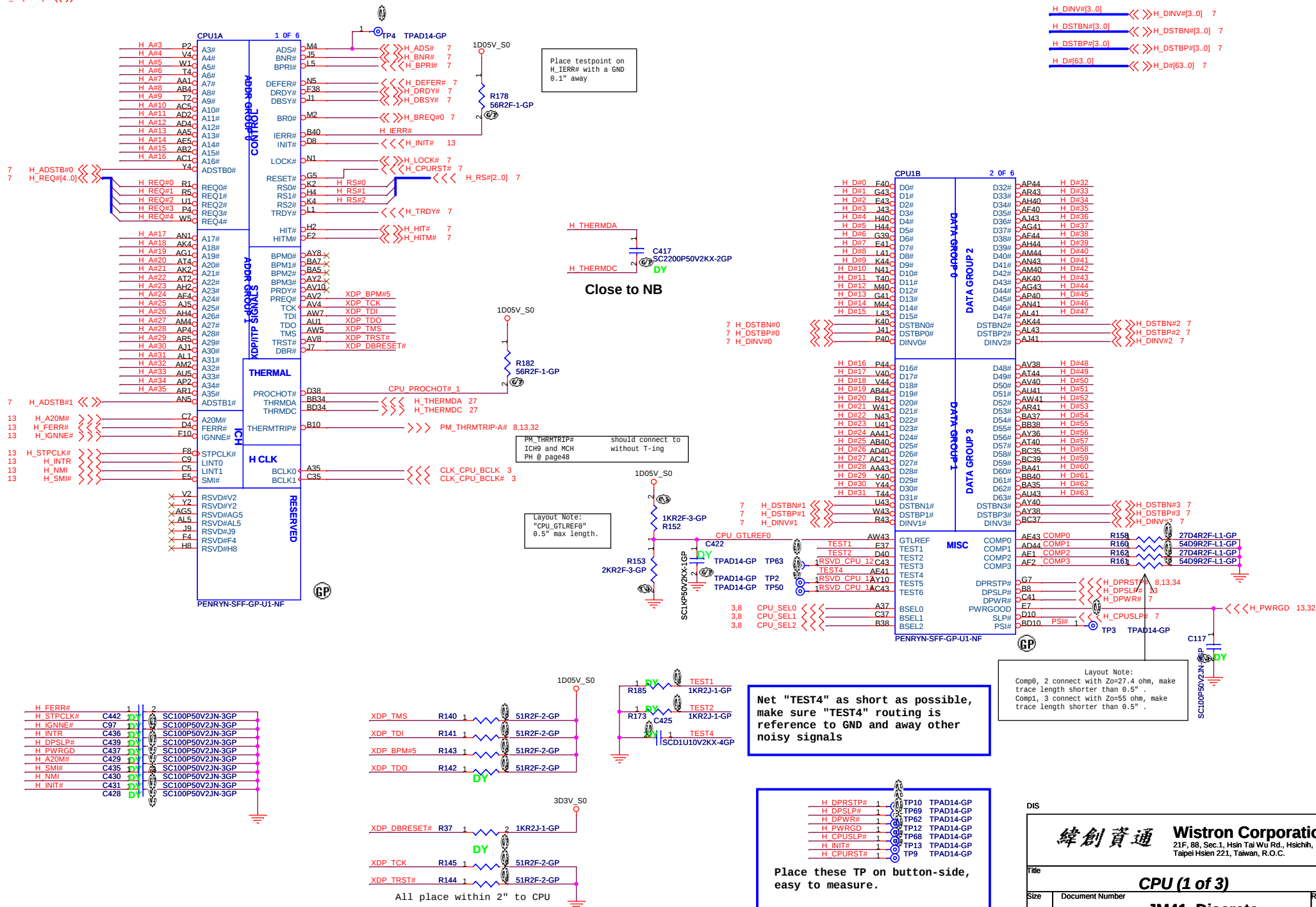
DIS

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Title: **Clock Generator**

Size: Document Number **JM41 Discrete** Rev **-2**

Date: Tuesday, April 28, 2009 Sheet 3 of 48



Net "TEST4" as short as possible,
make sure "TEST4" routing is
reference to GND and away other
noisy signals

Diagram showing the connection of TP pins to TPAD14-GP pins:

TP Pin	TPAD14-GP Pin
TP10	TPAD14-GP
TP69	TPAD14-GP
TP62	TPAD14-GP
TP12	TPAD14-GP
TP68	TPAD14-GP
TP13	TPAD14-GP
TP9	TPAD14-GP

TP pins are labeled: H DPRSTP#, H DPSLP#, H DPWR#, H PWRGD#, H CPUSLP#, H INIT#, H CPURST#.

Place these TP on button-side, easy to measure.

Layout Note:
Comp0, 2 connect with $Z_0=27.4\ \text{ohm}$, make trace length shorter than $0.5''$.
Comp1, 3 connect with $Z_0=55\ \text{ohm}$, make trace length shorter than $0.5''$.

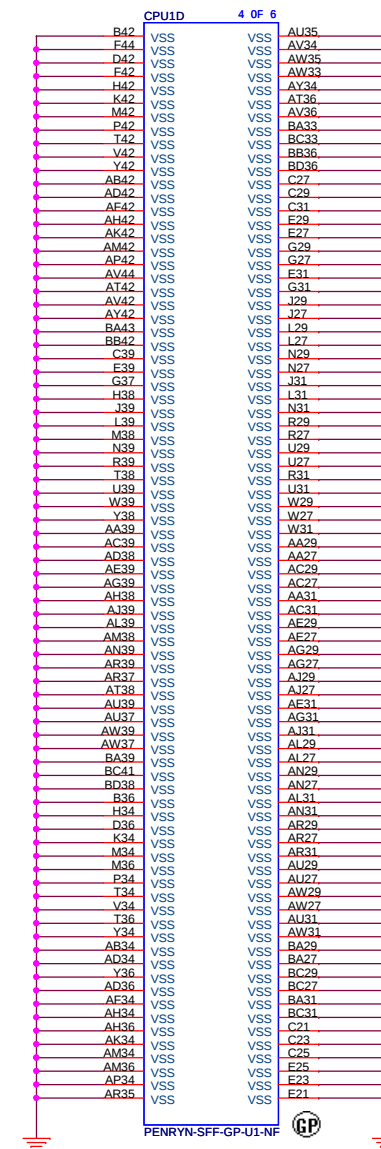
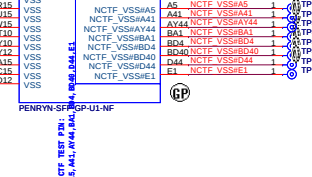
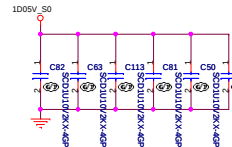
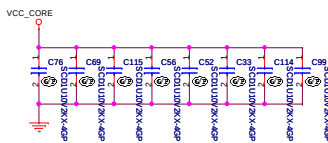
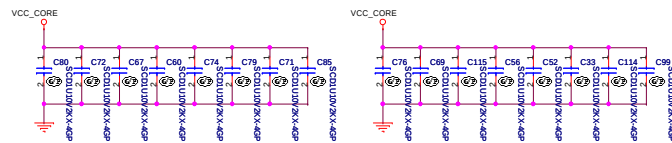
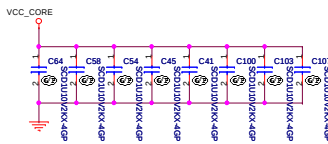
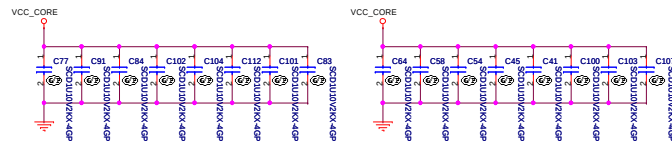
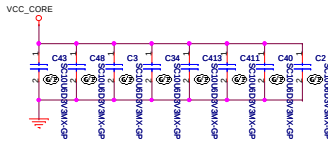
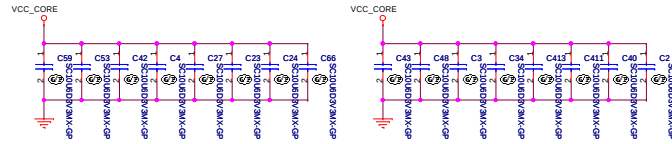
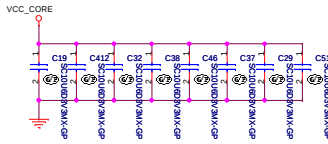
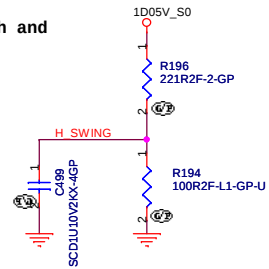


Figure 1 shows two schematic diagrams of 10-bit DACs. Diagram (a) shows a 10-bit DAC with 10 stages of current sources and capacitors. Diagram (b) shows a 10-bit DAC with 10 stages of current sources and capacitors, showing a different internal structure.



H_SWING routing Trace width and Spacing use 10 / 20 mil

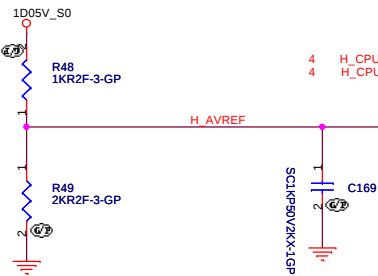
H_SWING Resistors and Capacitors close MCH 500 mil (MAX)



H_RCOMP routing Trace width and Spacing use 10 / 20 mil



Place them near to the chip (< 0.5"



H_SWING B6
H_RCOMP D4

4 H_CPURST# J11
4 H_CPUSLP# G9

H_AVREF L17
H_DVREF K18

CANTIGA-GS-GP-NF

NB1A 1 OF 10

H D#0 J7
H D#1 H6
H D#2 L11
H D#3 J3
H D#4 H4
H D#5 G3
H D#6 K10
H D#7 K12
H D#8 L1
H D#9 M10
H D#10 M6
H D#11 N11
H D#12 L7
H D#13 K6
H D#14 M4
H D#15 K4
H D#16 P6
H D#17 W9
H D#18 V6
H D#19 V2
H D#20 P10
H D#21 W7
H D#22 N9
H D#23 P4
H D#24 U9
H D#25 V4
H D#26 U1
H D#27 W3
H D#28 V10
H D#29 U7
H D#30 W11
H D#31 U11
H D#32 AC11
H D#33 AC9
H D#34 V4
H D#35 Y10
H D#36 AB6
H D#37 AA9
H D#38 AB10
H D#39 AA1
H D#40 AC3
H D#41 AC7
H D#42 AD12
H D#43 AB4
H D#44 Y6
H D#45 AD10
H D#46 AA11
H D#47 AB2
H D#48 AD4
H D#49 AE7
H D#50 AD2
H D#51 AD6
H D#52 AE3
H D#53 AC9
H D#54 AG7
H D#55 AE11
H D#56 AK6
H D#57 AF6
H D#58 AJ9
H D#59 AH6
H D#60 AE12
H D#61 AH4
H D#62 AJ7
H D#63 AE9

HOST

H_A#_3
H_A#_4
H_A#_5
H_A#_6
H_A#_7
H_A#_8
H_A#_9
H_A#_10
H_A#_11
H_A#_12
H_A#_13
H_A#_14
H_A#_15
H_A#_16
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H_A#_28
H_A#_29
H_A#_30
H_A#_31
H_A#_32
H_A#_33
H_A#_34
H_A#_35

H_ADS#
H_ADSTB#_0
H_ADSTB#_1
H_BNR#
H_BPRI#
H_BREQ#
H_DEFER#
H_DBSY#
HPLL_CLK#
H_DPWR#
H_DRDY#
H_HIT#
H_HITM#
H_LOCK#
H_TRDY#

H_DINV#_0
H_DINV#_1
H_DINV#_2
H_DINV#_3

H_DSTBN#_0
H_DSTBN#_1
H_DSTBN#_2
H_DSTBN#_3

H_DSTBP#_0
H_DSTBP#_1
H_DSTBP#_2
H_DSTBP#_3

H_REQ#_0
H_REQ#_1
H_REQ#_2
H_REQ#_3
H_REQ#_4

H_RS#_0
H_RS#_1
H_RS#_2

H_A#[35..3] <<>> H_A#[35..3] 4

H_ADS# 4
H_ADSTB#0 4
H_ADSTB#1 4
H_BNR# 4
H_BPRI# 4
H_BREQ#0 4
H_DEFER# 4
H_DBSY# 4
CLK_MCH_BCLK# 3
CLK_MCH_BCLK# 3
H_DPWR# 4
H_DRDY# 4
H_HIT# 4
H_HITM# 4
H_LOCK# 4
H_TRDY# 4

H_DINV#[3..0] <<>> H_DINV#[3..0] 4

H_DSTBN#[3..0] <<>> H_DSTBN#[3..0] 4

H_DSTBP#[3..0] <<>> H_DSTBP#[3..0] 4

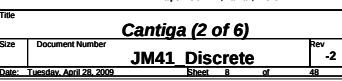
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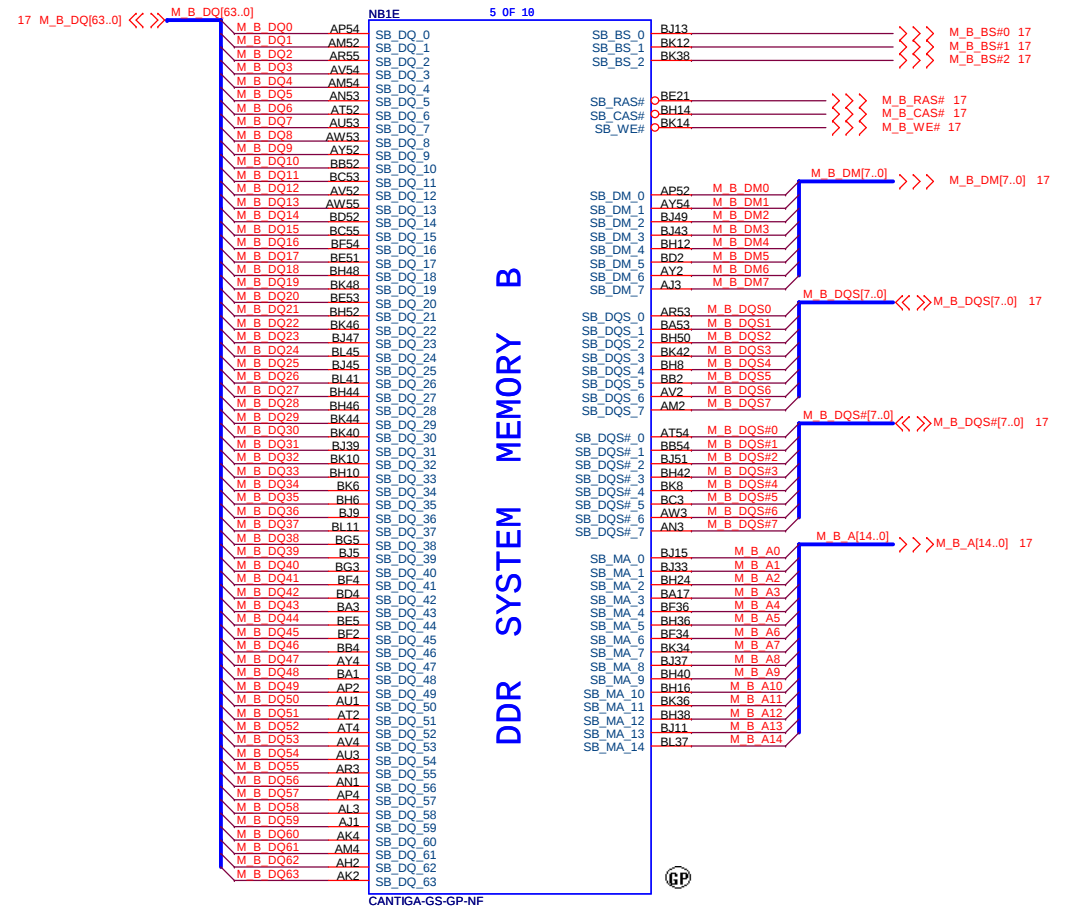
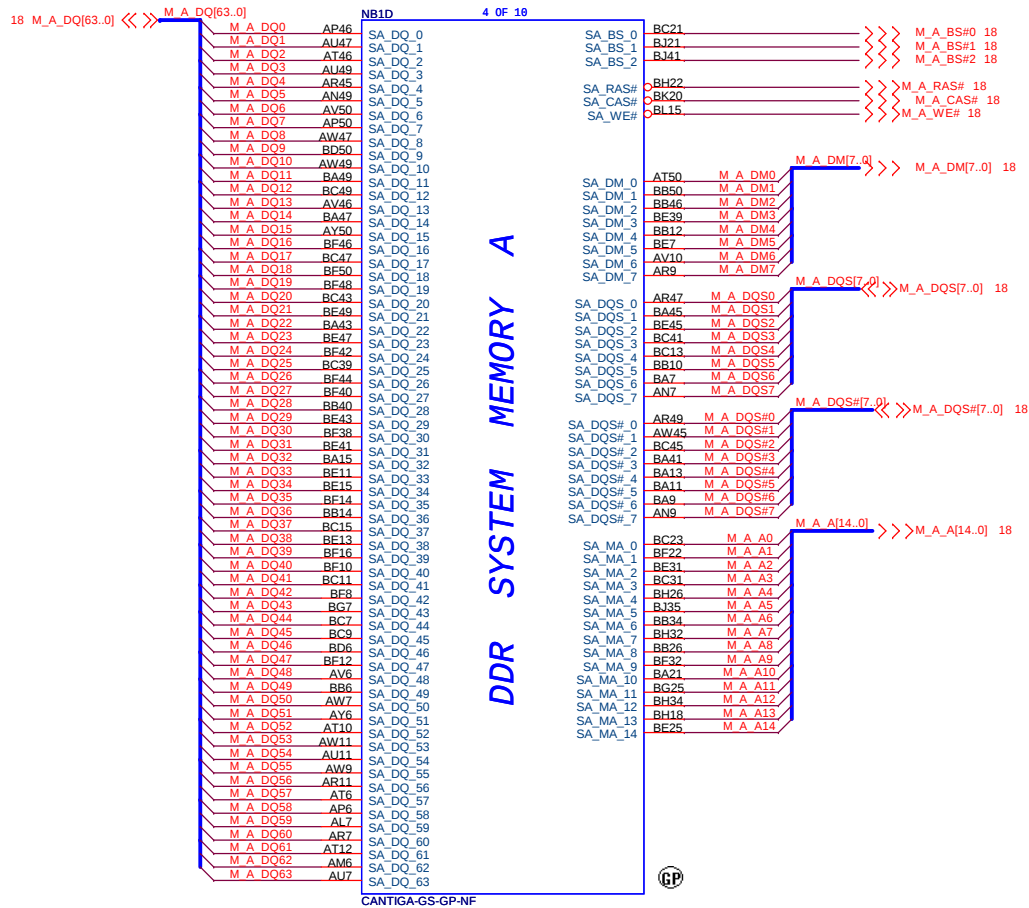
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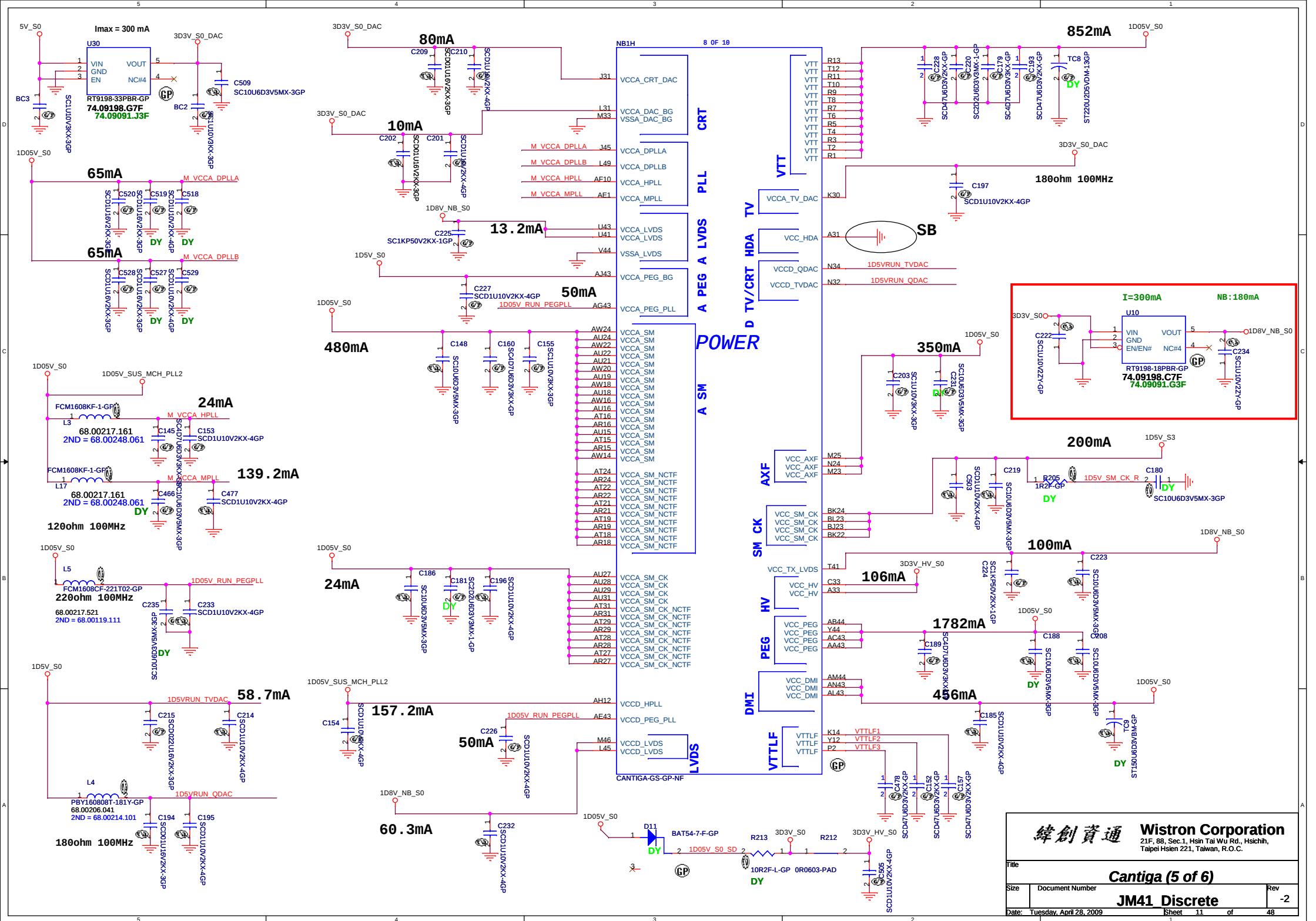
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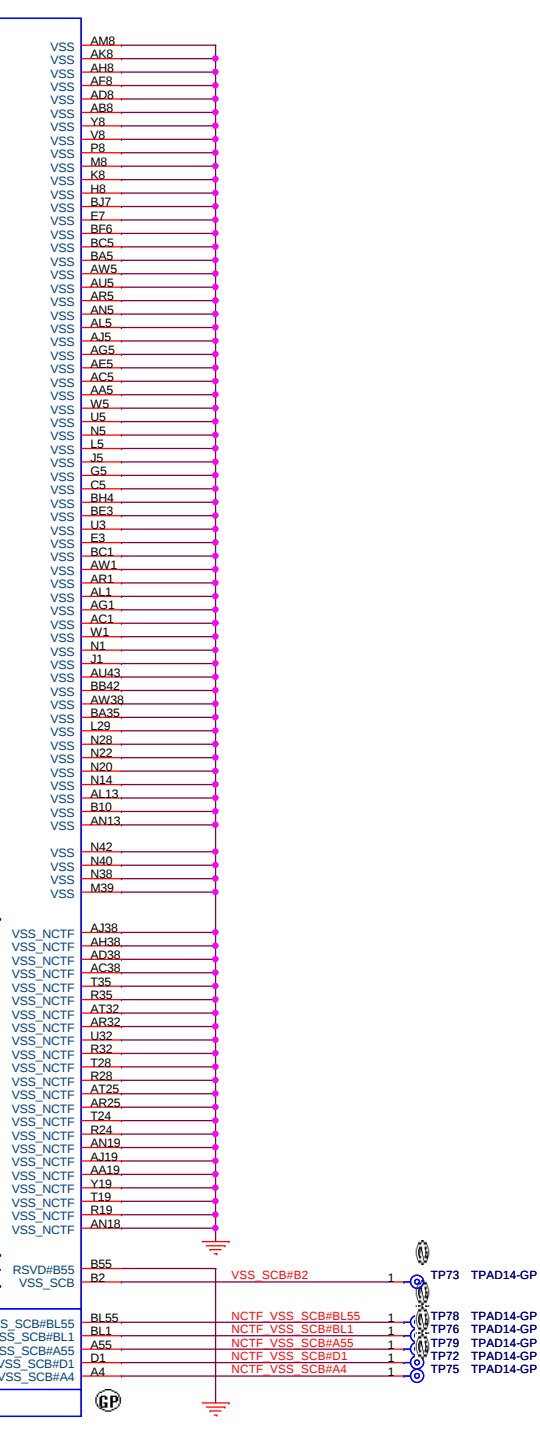
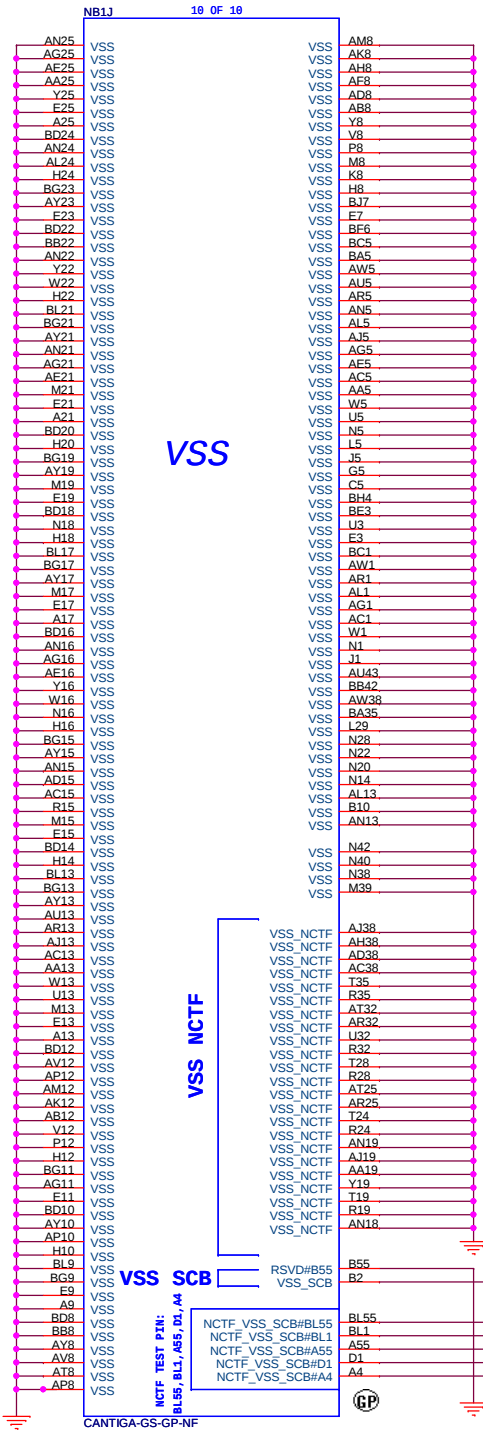
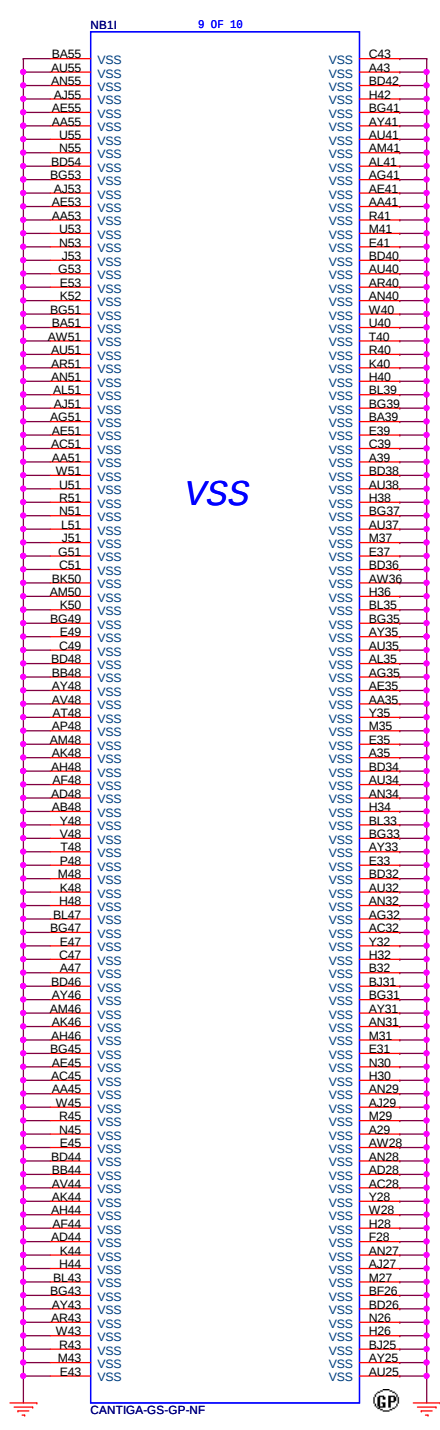
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Title
Size Document Number
Date: Tuesday, April 28, 2009
Cantiga (1 of 6)
JM41 Discrete
Rev
-2
Sheet 7 of 48

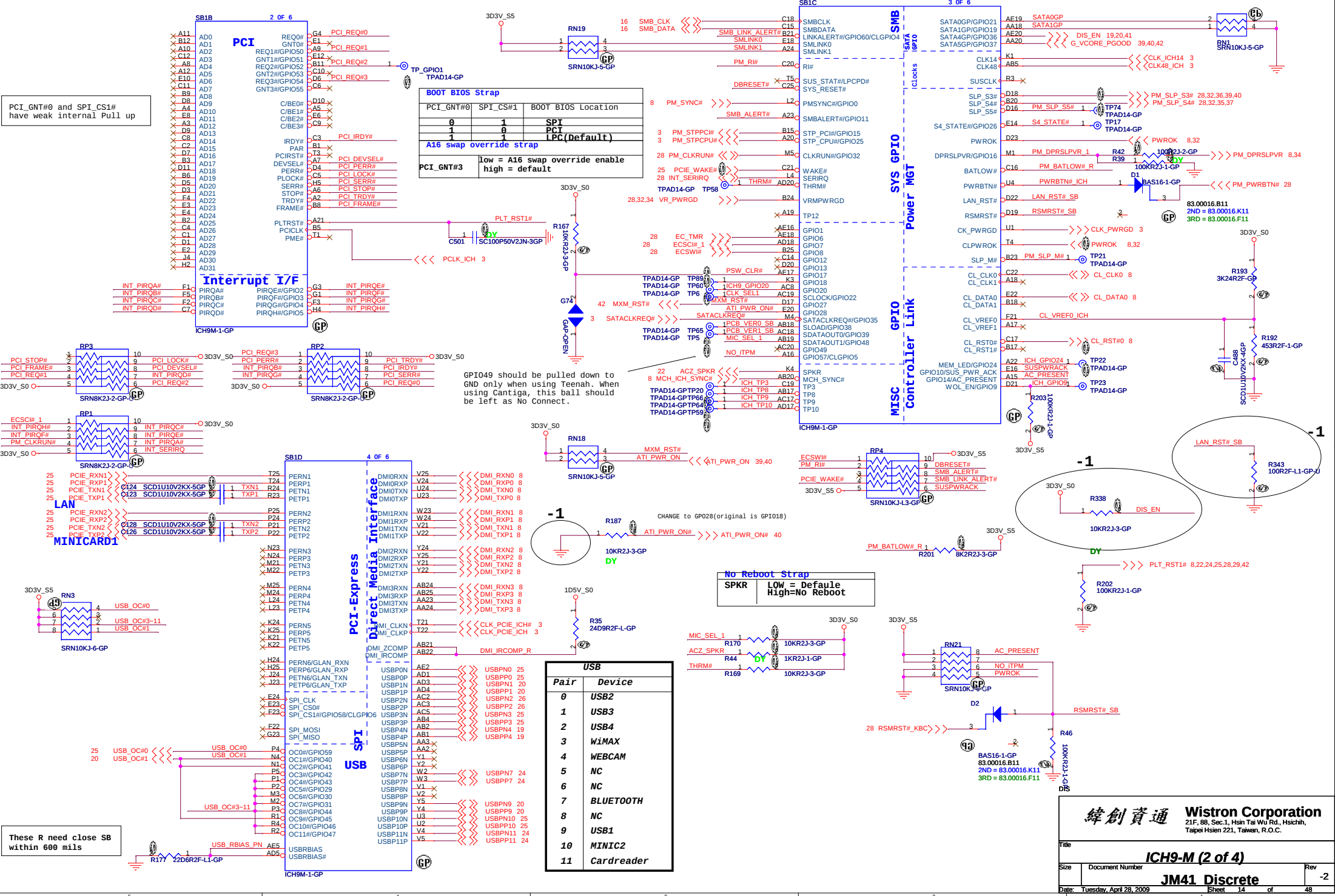








PCI_GNT#0 and SPI_CS1#
have weak internal Pull up



657mA

*Within a given well, 5VREF needs to be up before the corresponding 3.3V rail

2mA

2mA

47mA

SATA+USB=1.56A

USBPLL=10mA

23mA

80mA

1mA

1.13A

23mA

50mA

1mA

VCC3_3=278mA

32mA

32mA

177mA

18mA

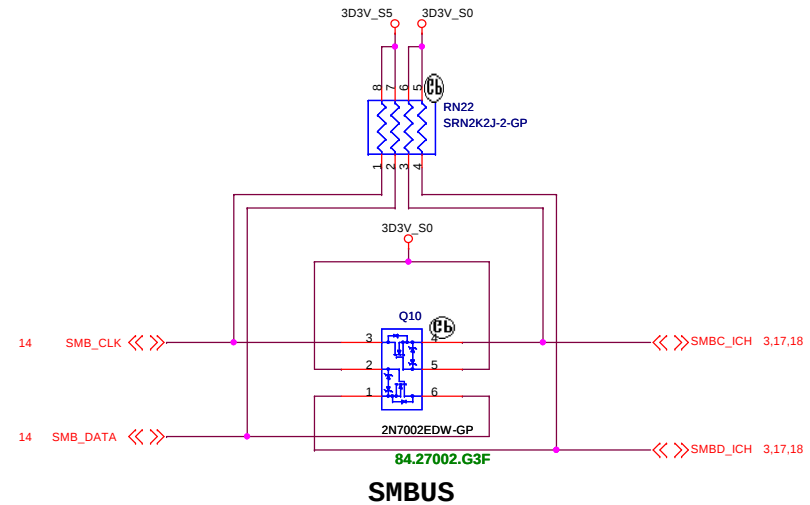
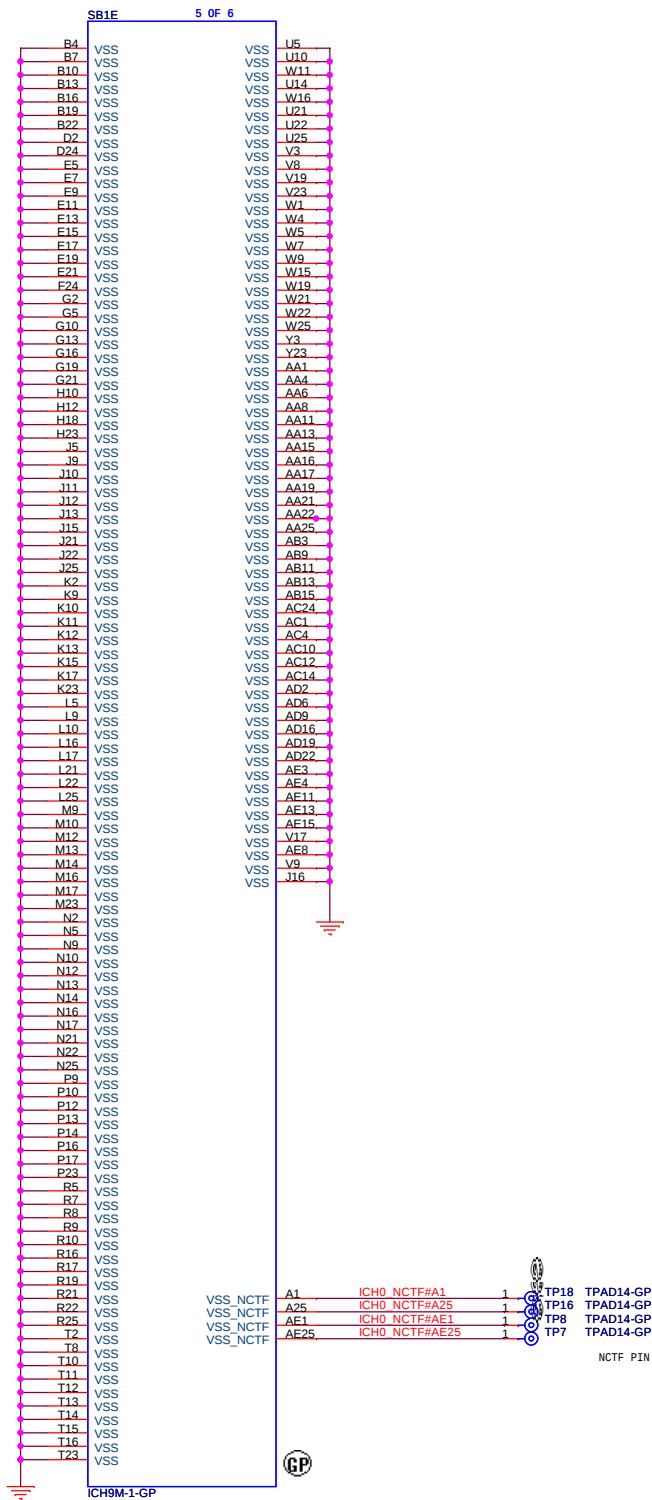
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Wistron Corporation

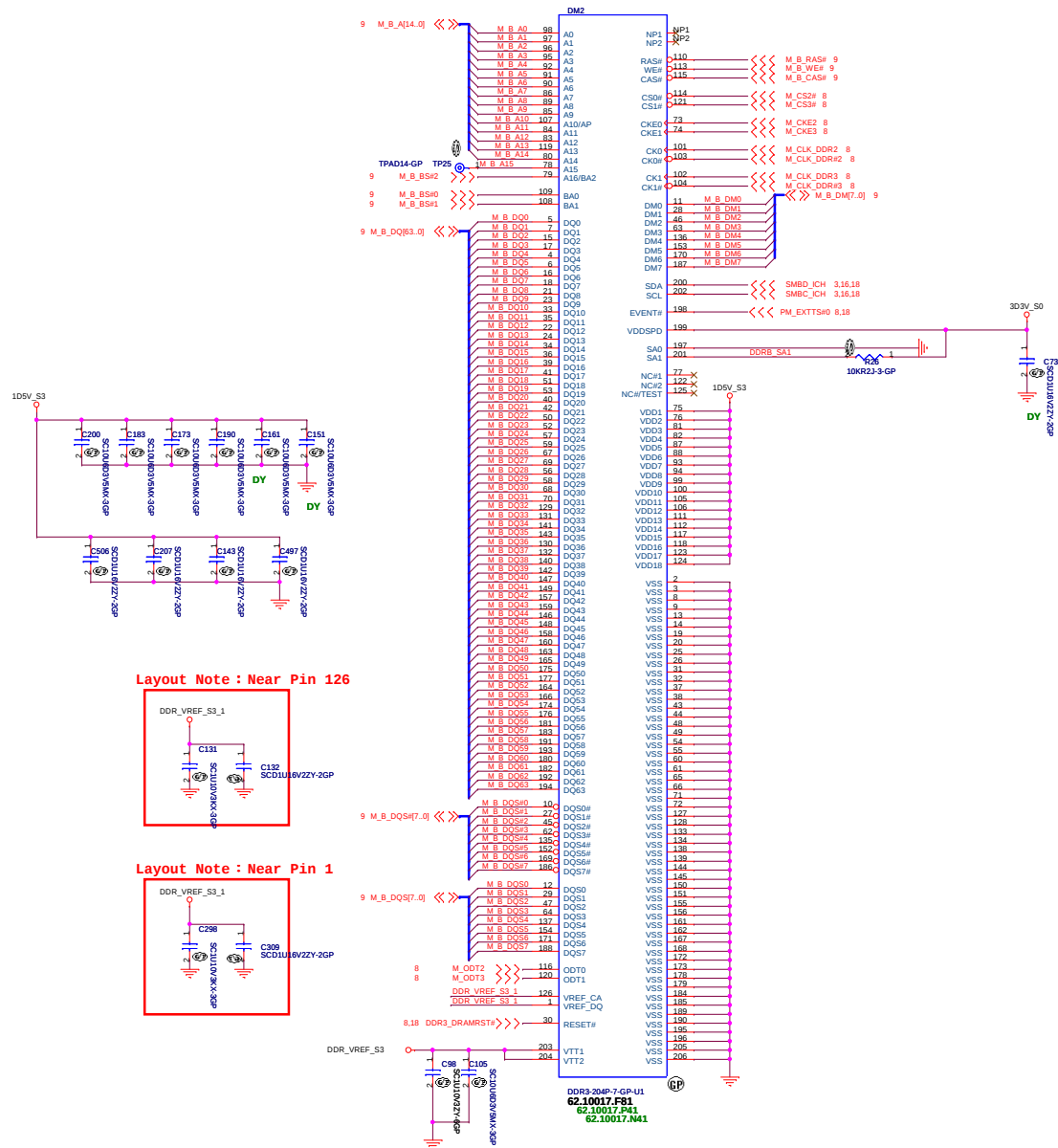
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Title			ICH9-M (3 of 4)
Size	Document Number	Rev	
		JM41 Discrete	
Date:	Tuesday, April 28, 2009	Sheet	15 of 48

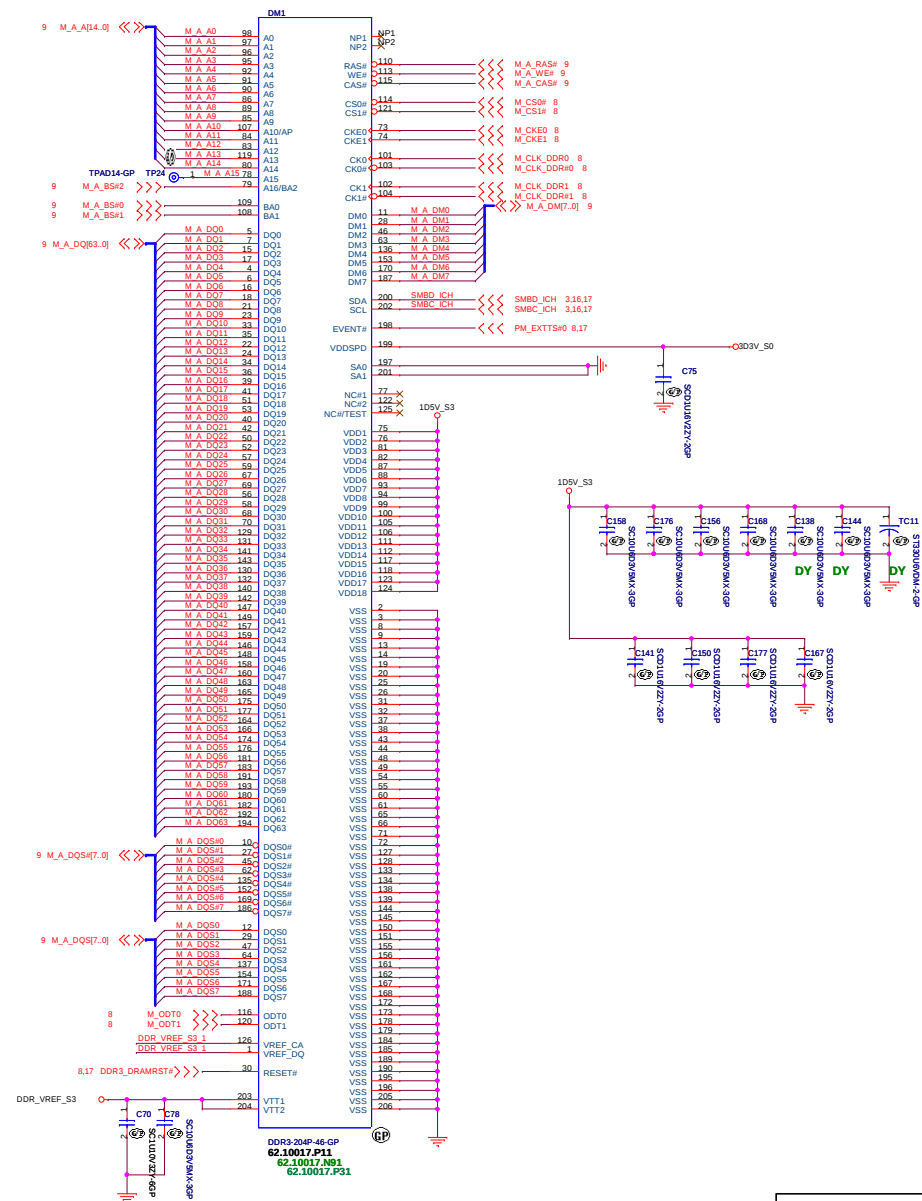
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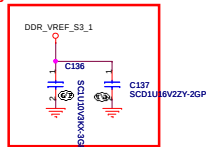
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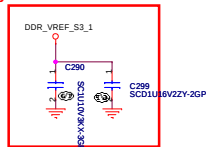
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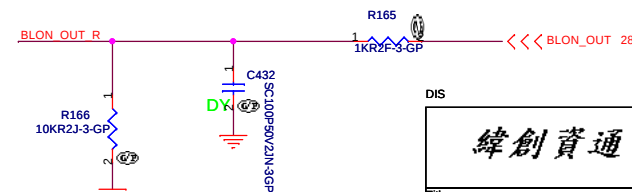
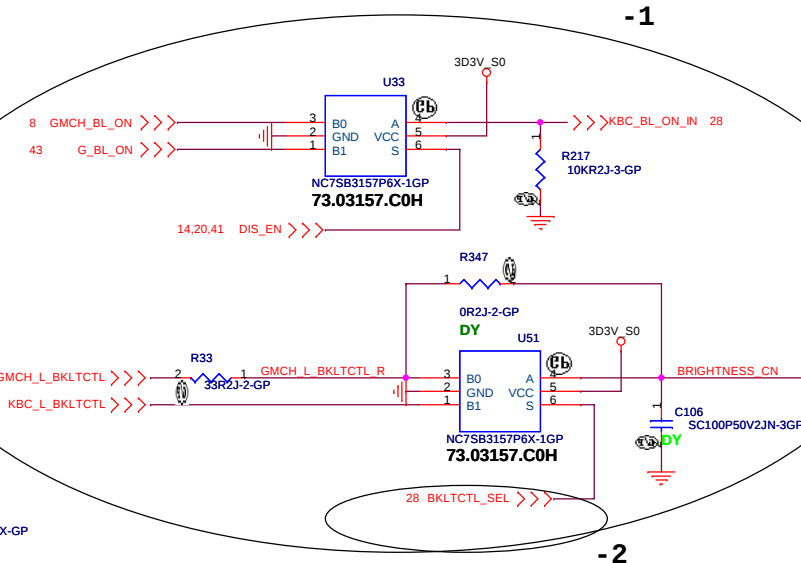
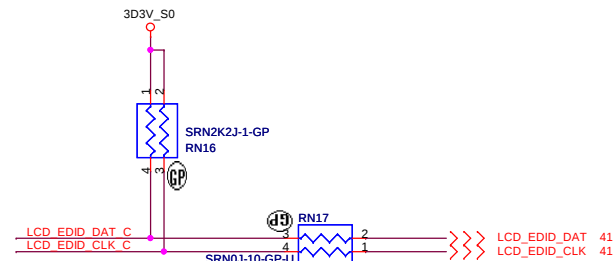
Layout Note : Near Pin 126



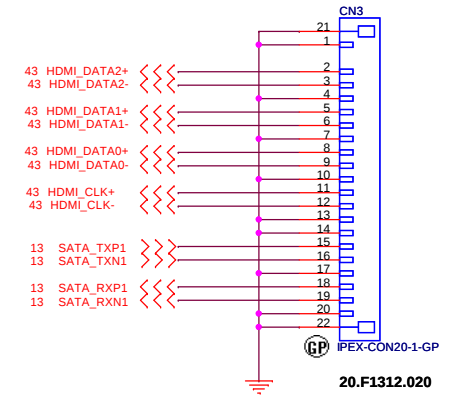
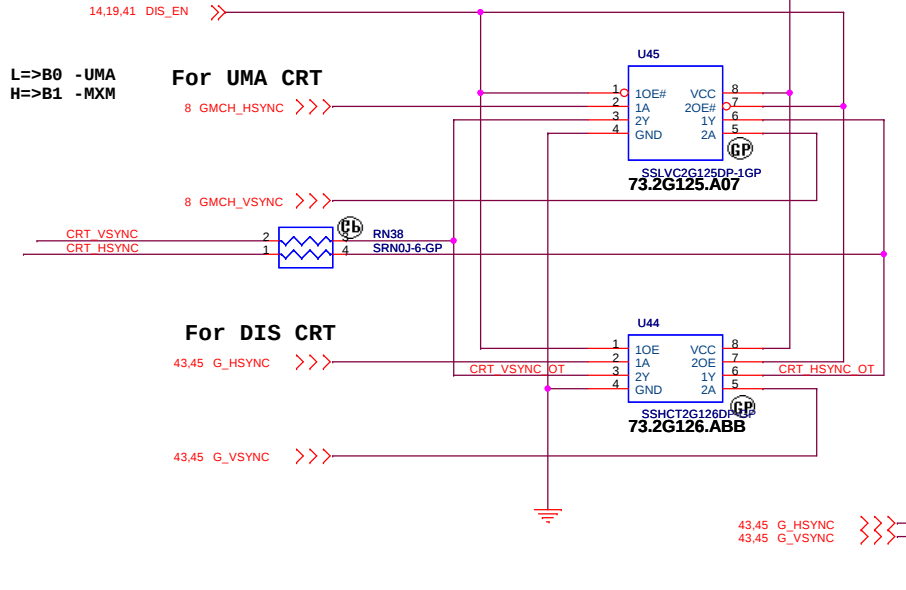
Layout Note : Near Pin 1



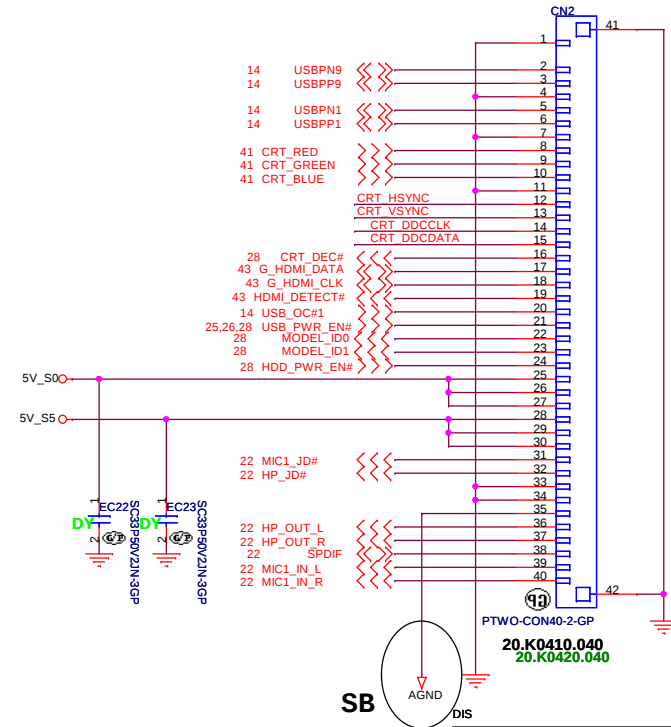
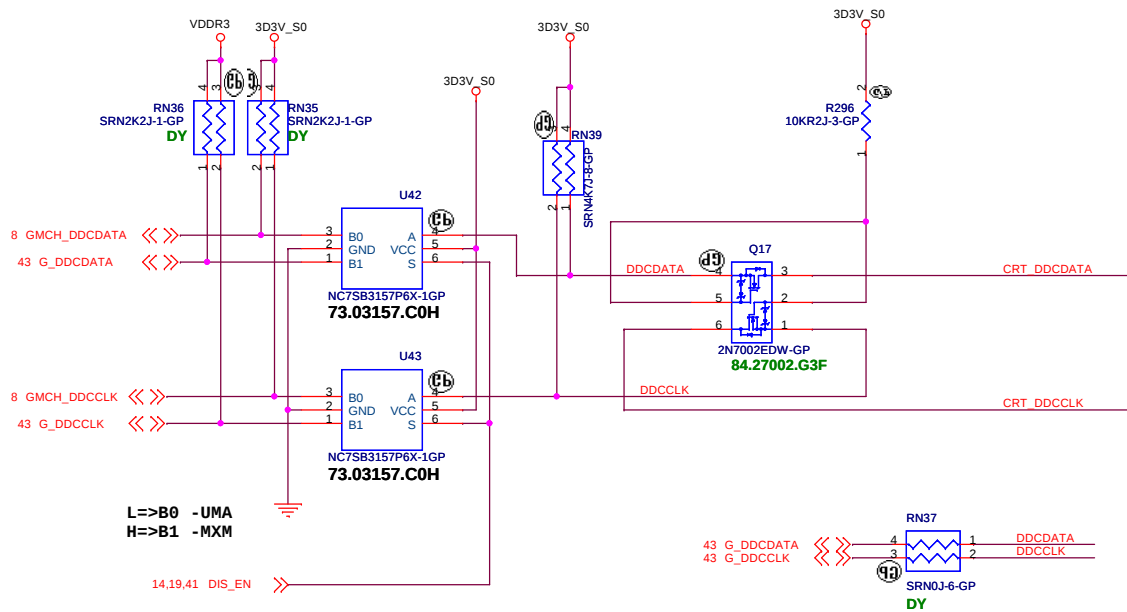
Internal MIC



Hsync & Vsync level shift

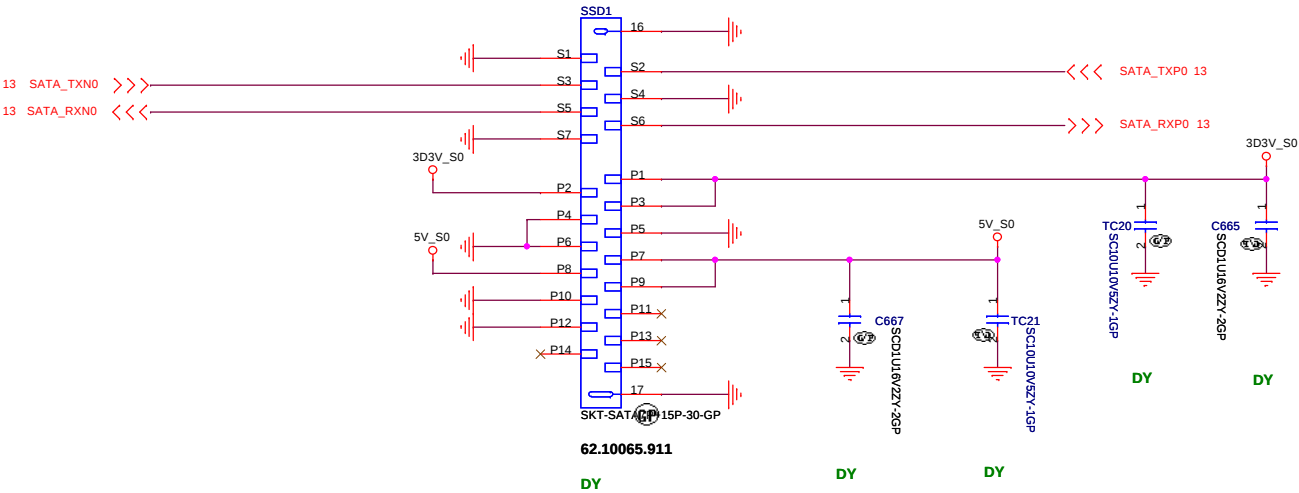


DDC_CLK & DATA level shift

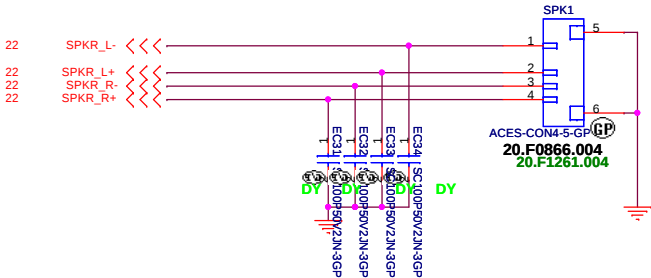


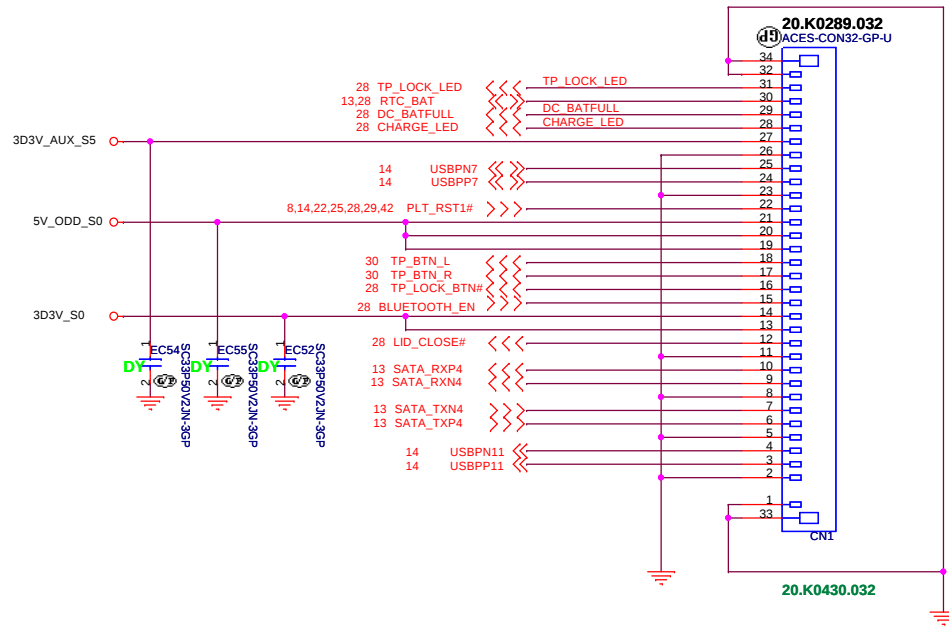
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

SSD SATA Connector



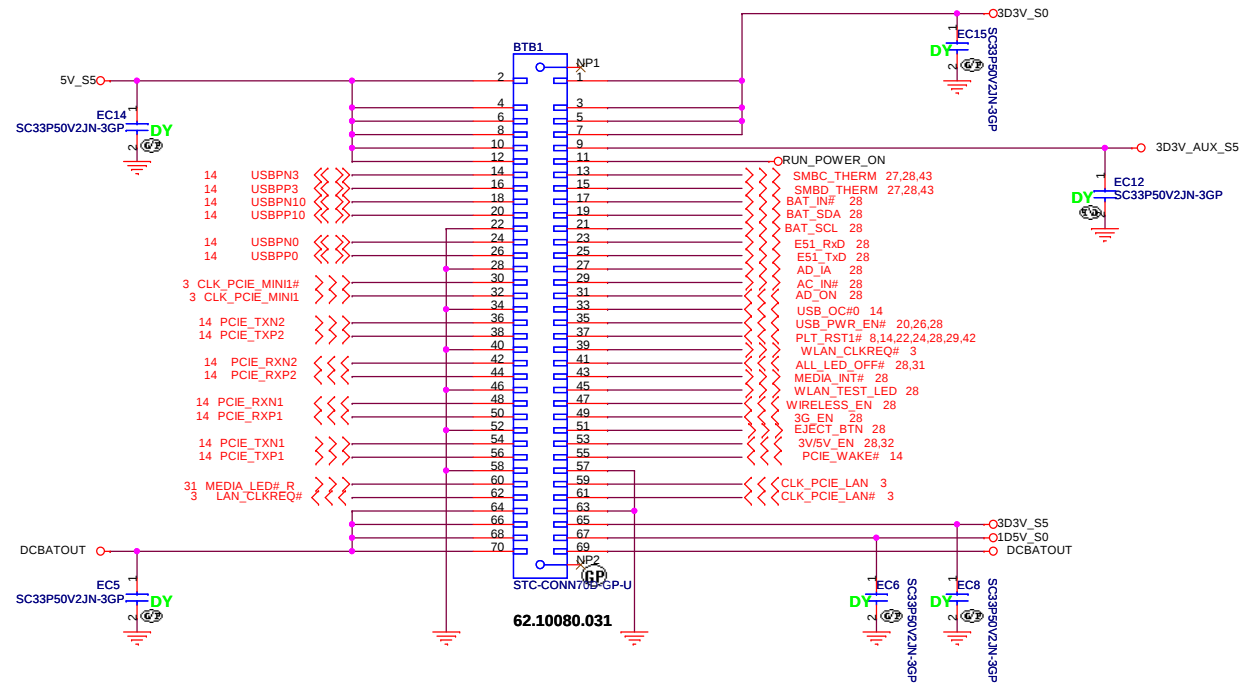
Internal Speaker





DIS

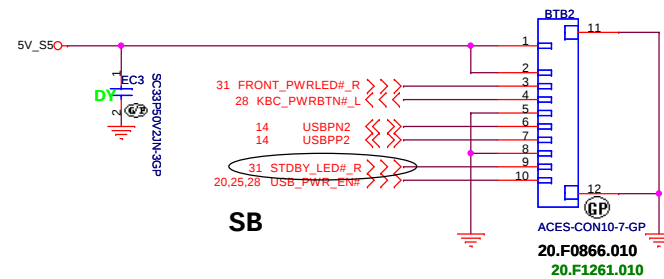
緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title CARDREADER BD CONN			
Size	Document Number		Rev
	JM41 Discrete		-2
Date: Tuesday, April 28, 2009	Sheet	24 of	48

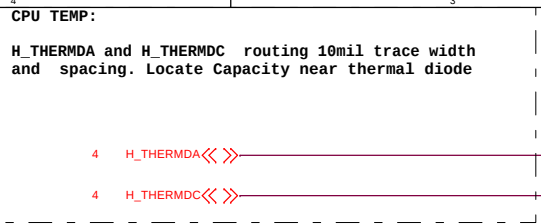
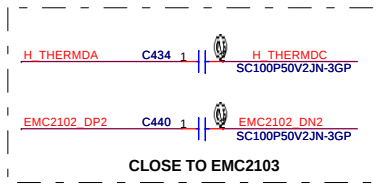


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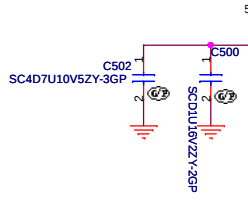
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		MINI BD CONN	
Size	Document Number	Rev	
A3	JM41_Discrete	-2	
Date:	Tuesday, April 28, 2009	Sheet	25 of 48

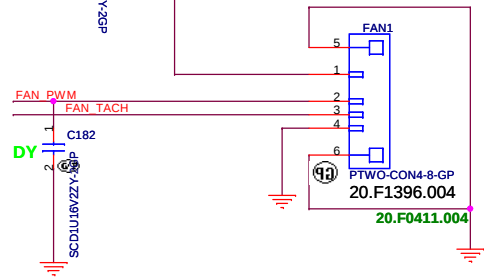
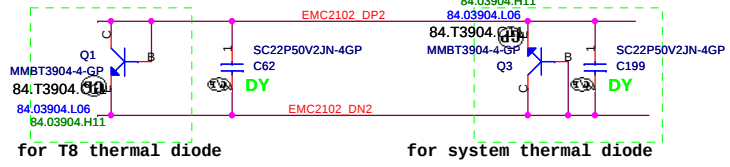
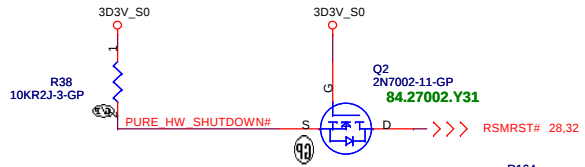




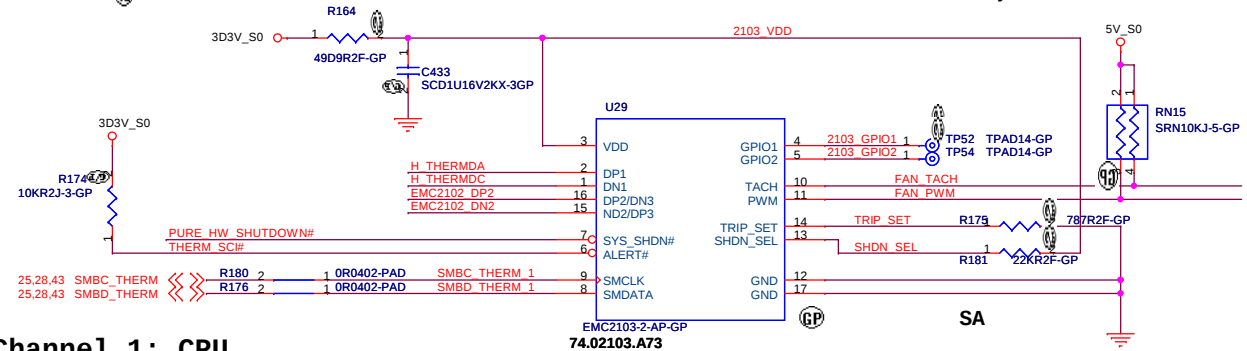
for CPU thermal diode



C587 for EMI and solve acoustic noise



ps. FAN1 POWER TRACE WIDTH MAY BE IN 25 MIL



Channel 1: CPU
Channel 2: Palmrest
Channel 3: T8

SHDN SEL

PULL UP RESISTOR	MODE OF OPERATION
<=4.7K OHM	EXTERNAL DIODE 1 SIMPLE MODE-BETA COMPENSATION DISABLED, REC DISABLED
6.8K OHM	EXTERNAL DIODE 1 DIODE MODE-BETA COMPENSATION DISABLED, REC ENABLED
10K OHM	EXTERNAL DIODE 1 TRANSISTOR MODE-BETA COMPENSATION ENABLED, REC ENABLED
15K OHM	INTERNAL DIODE
22K OHM	EXTERNAL DIODE 2 TRANSISTOR MODE-BETA COMPENSATION ENABLED, REC ENABLED
>=33K OHM	EXTERNAL DIODE 1 TRANSISTOR MODE-BETA COMPENSATION ENABLED, REC ENABLED

TRIP SET

Ttrip(degree)	RSET(1%)
85	562
86	604
87	649
88	698
89	750
90	787
91	845
92	909
93	953
94	1020
95	1100

DIS

緯創資通

Wistron Corporation

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Title

Thermal/Fan Controllor

Size

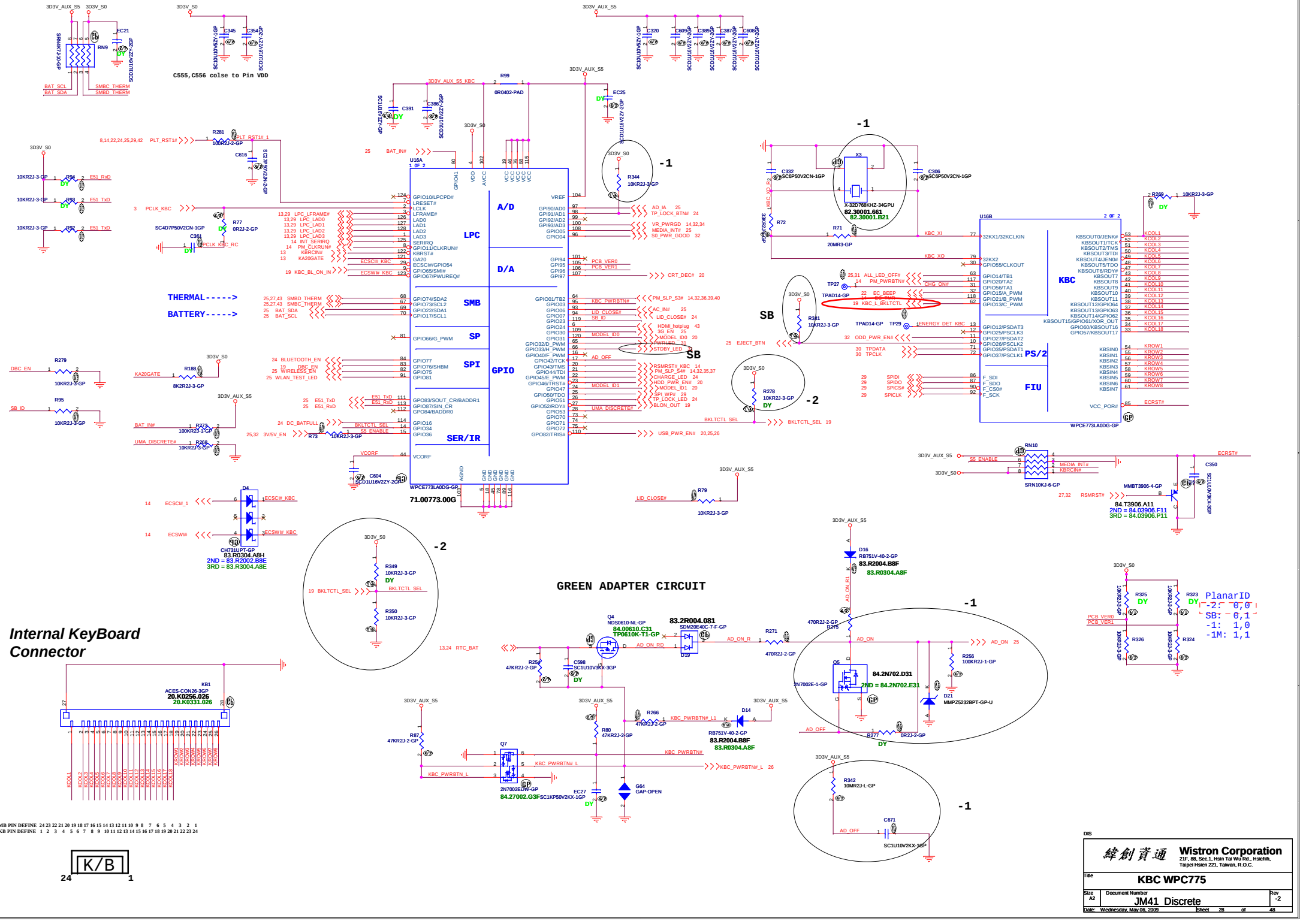
Document Number

Rev

-2

Date: Tuesday, April 28, 2009

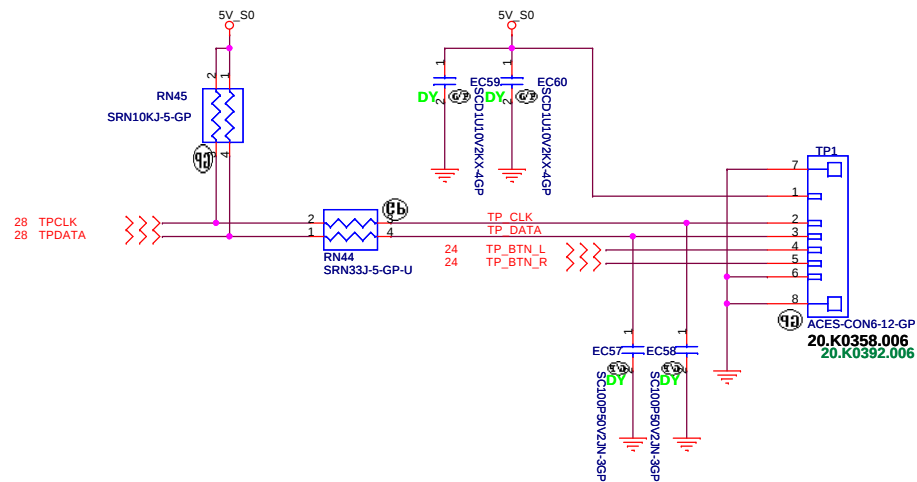
Sheet 27 of 48



MB PIN DEFINE: 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1
KB PIN DEFINE: 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24

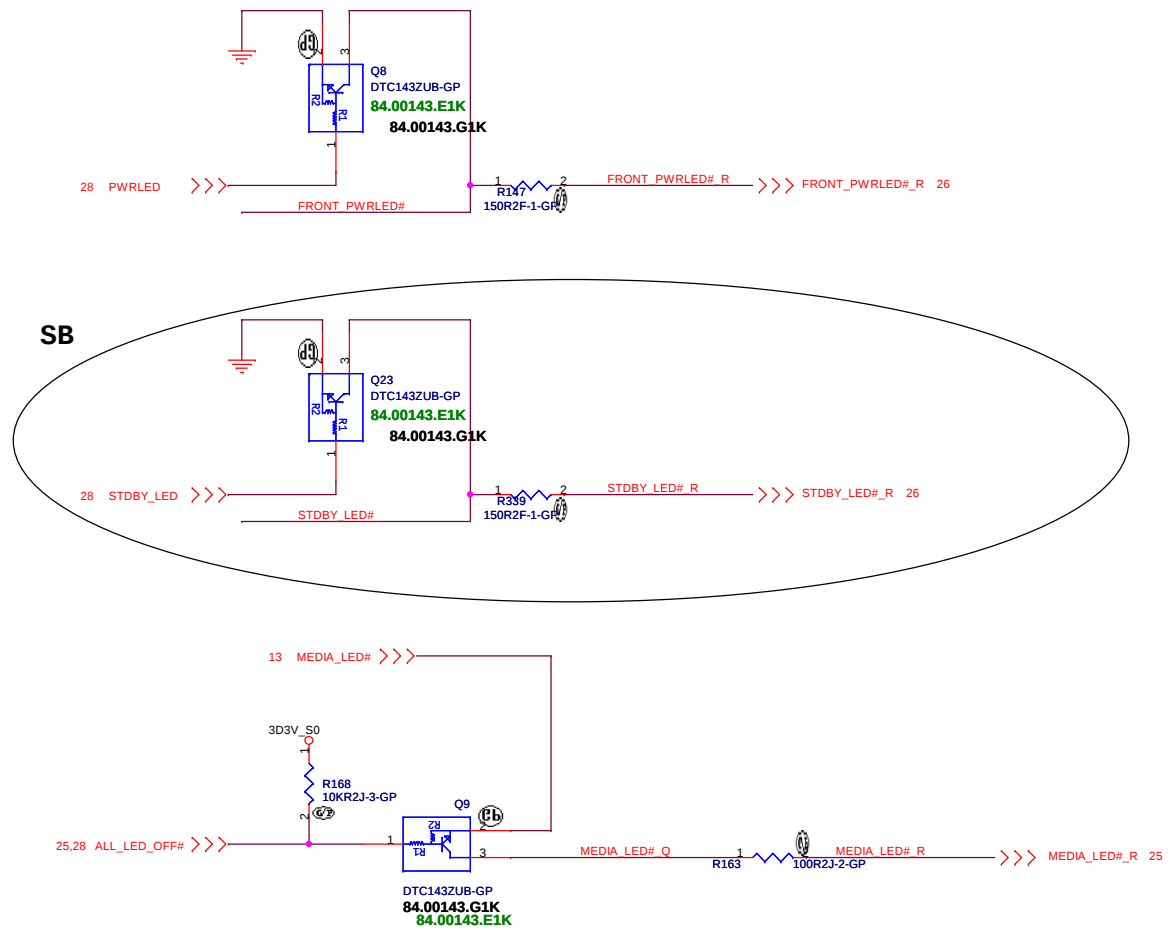
24 **K/B** 1

TOUCH PAD

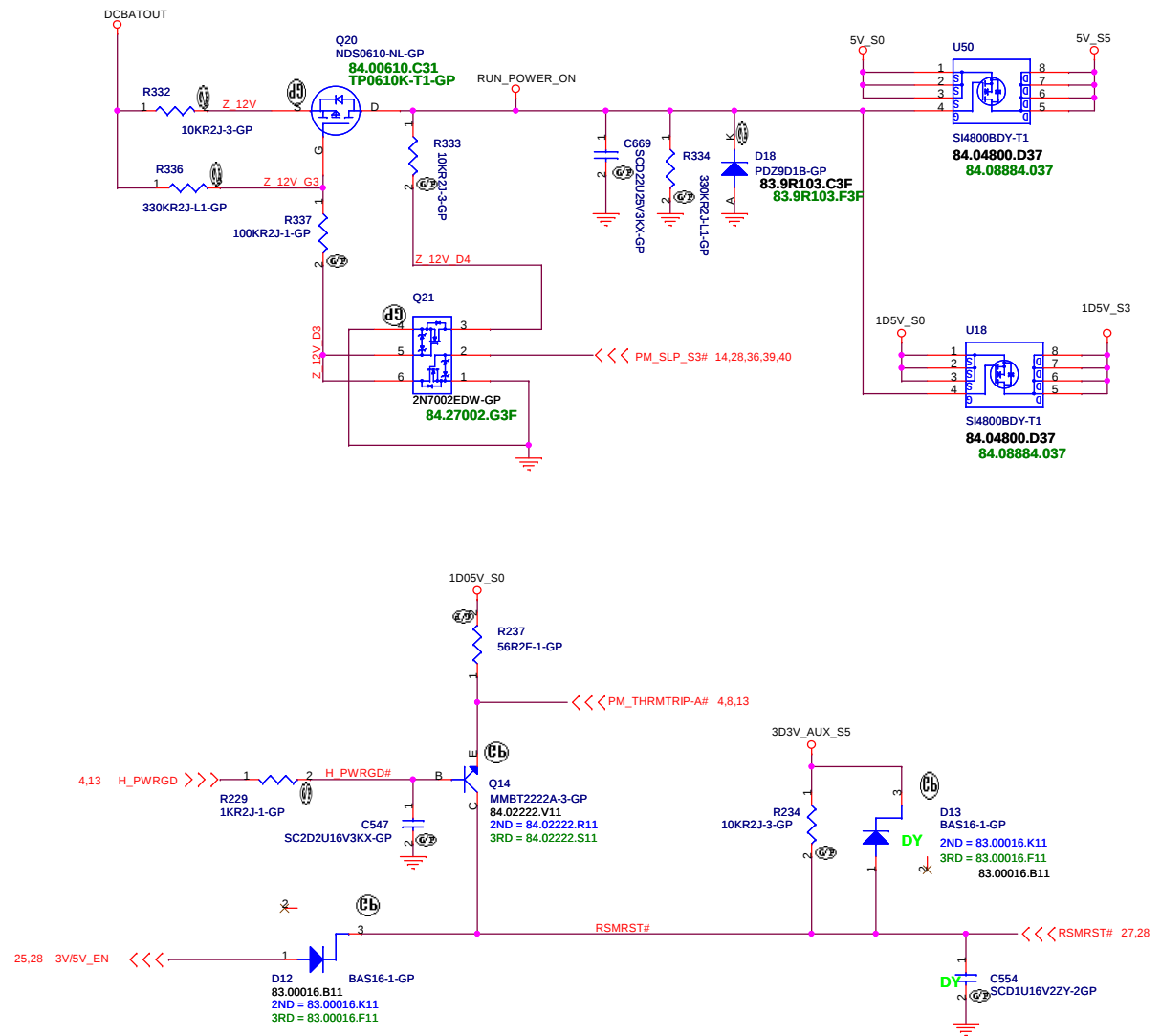


DIS

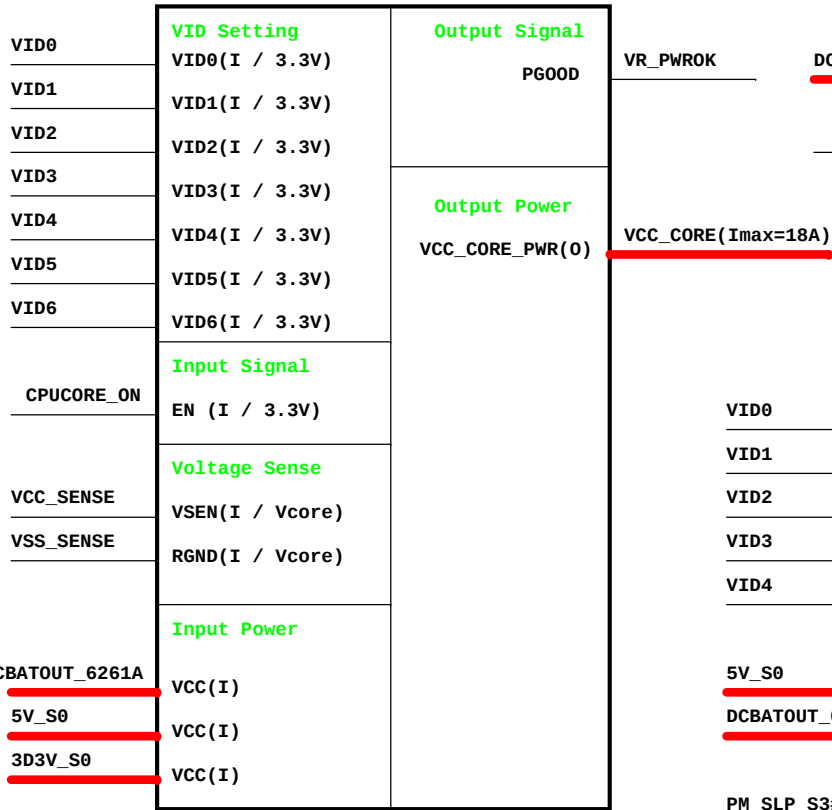
緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Touch PAD			
Size	Document Number		Rev
	JM41 Discrete		-2
Date: Tuesday, April 28, 2009		Sheet 30 of 48	



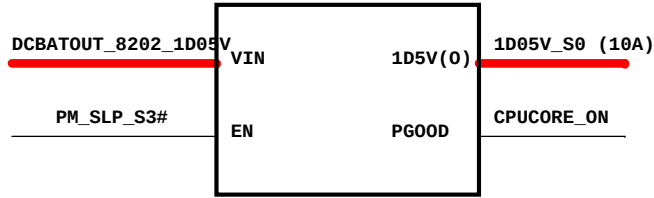
Run Power



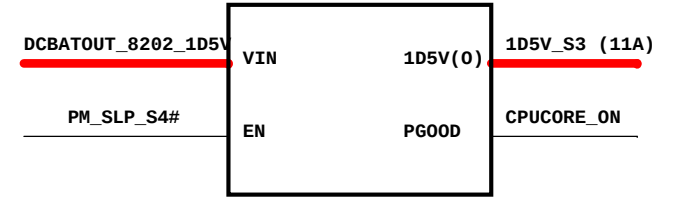
CPU_CORE
ISL6261A



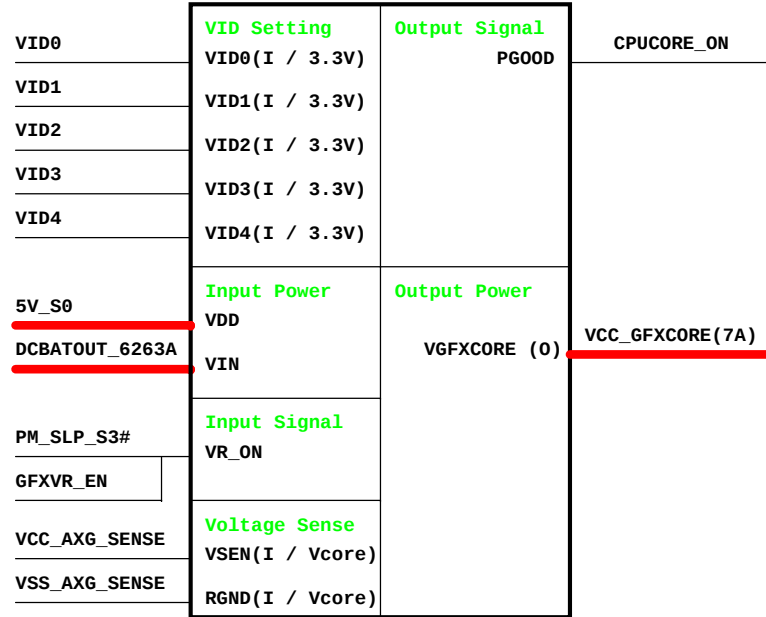
RT8202 1D05V_S0



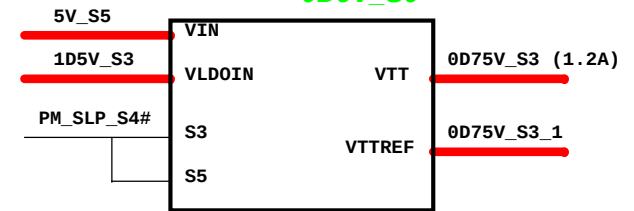
RT8202 1D5V_S3



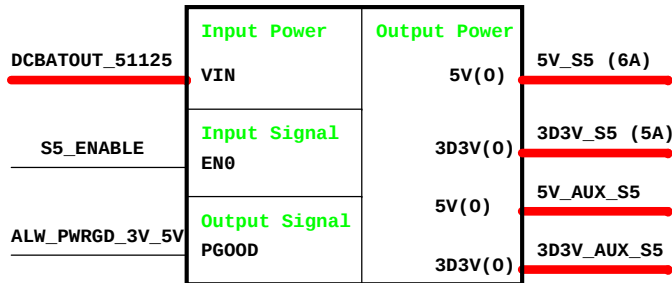
GFX_CORE
ISL6263A



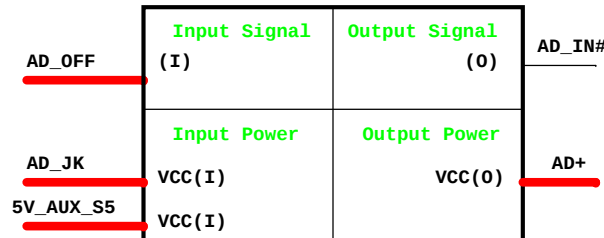
RT9026 0D9V_S0



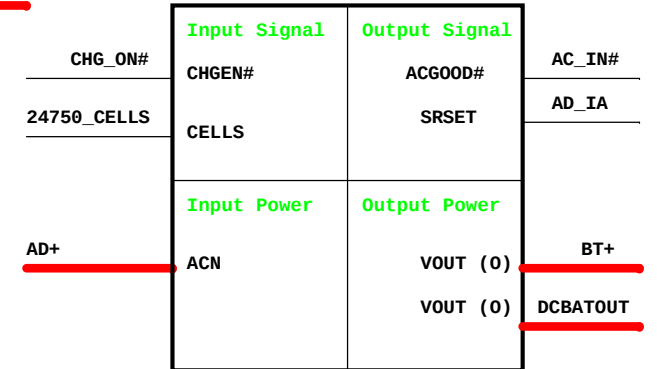
TPS51125
5V/3D3V



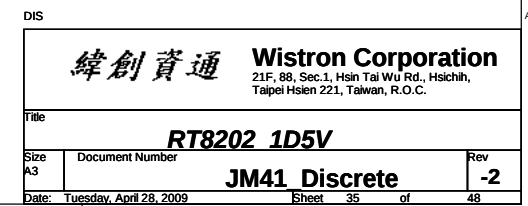
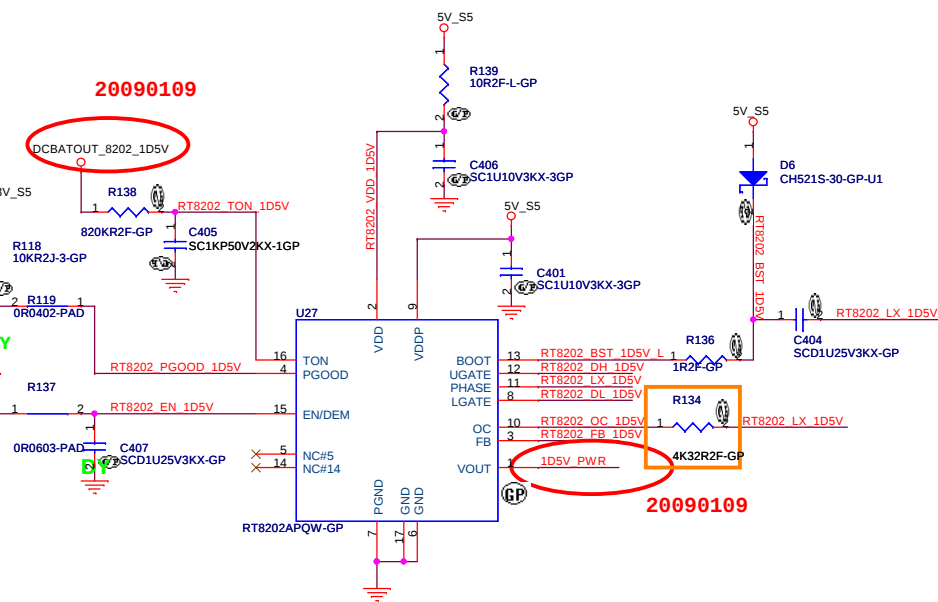
Adapter

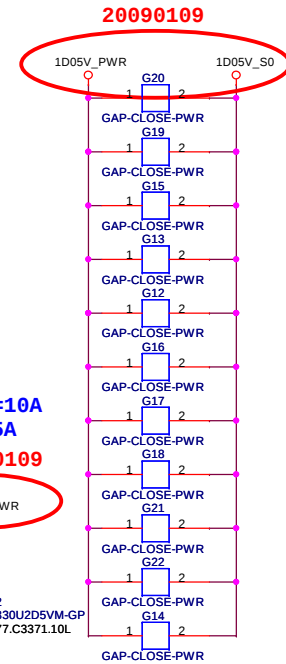
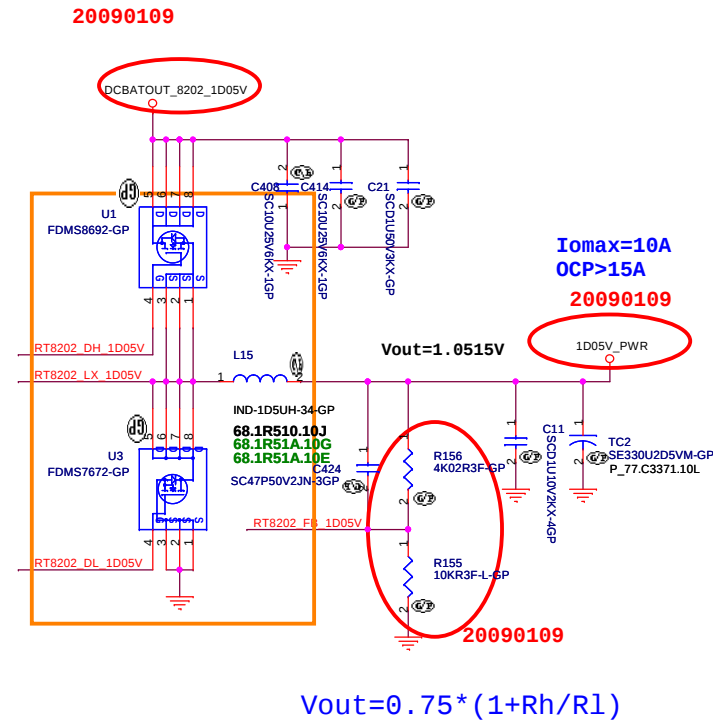
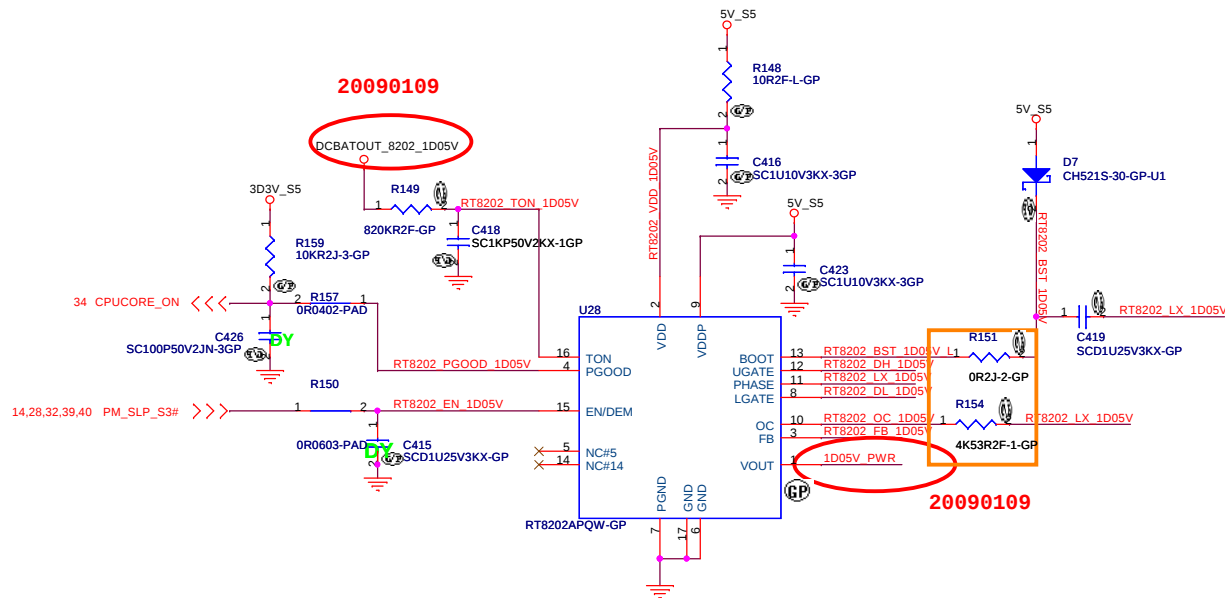
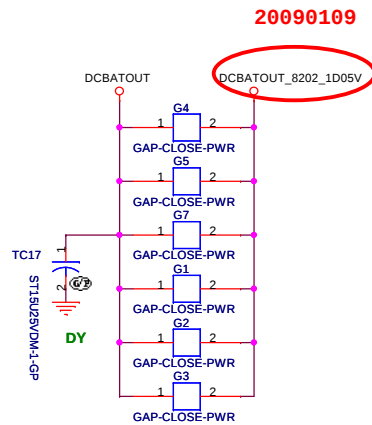


Charger MAX8731A



緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

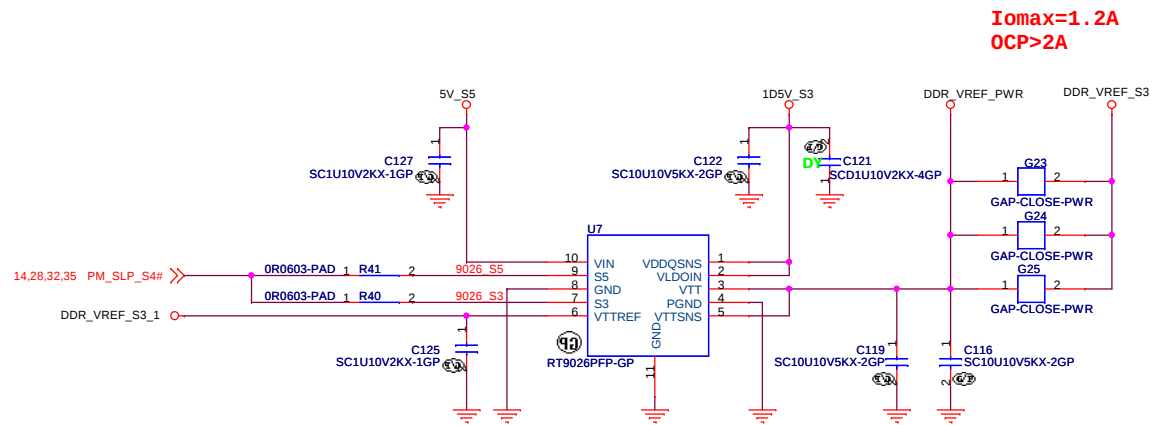




DIS

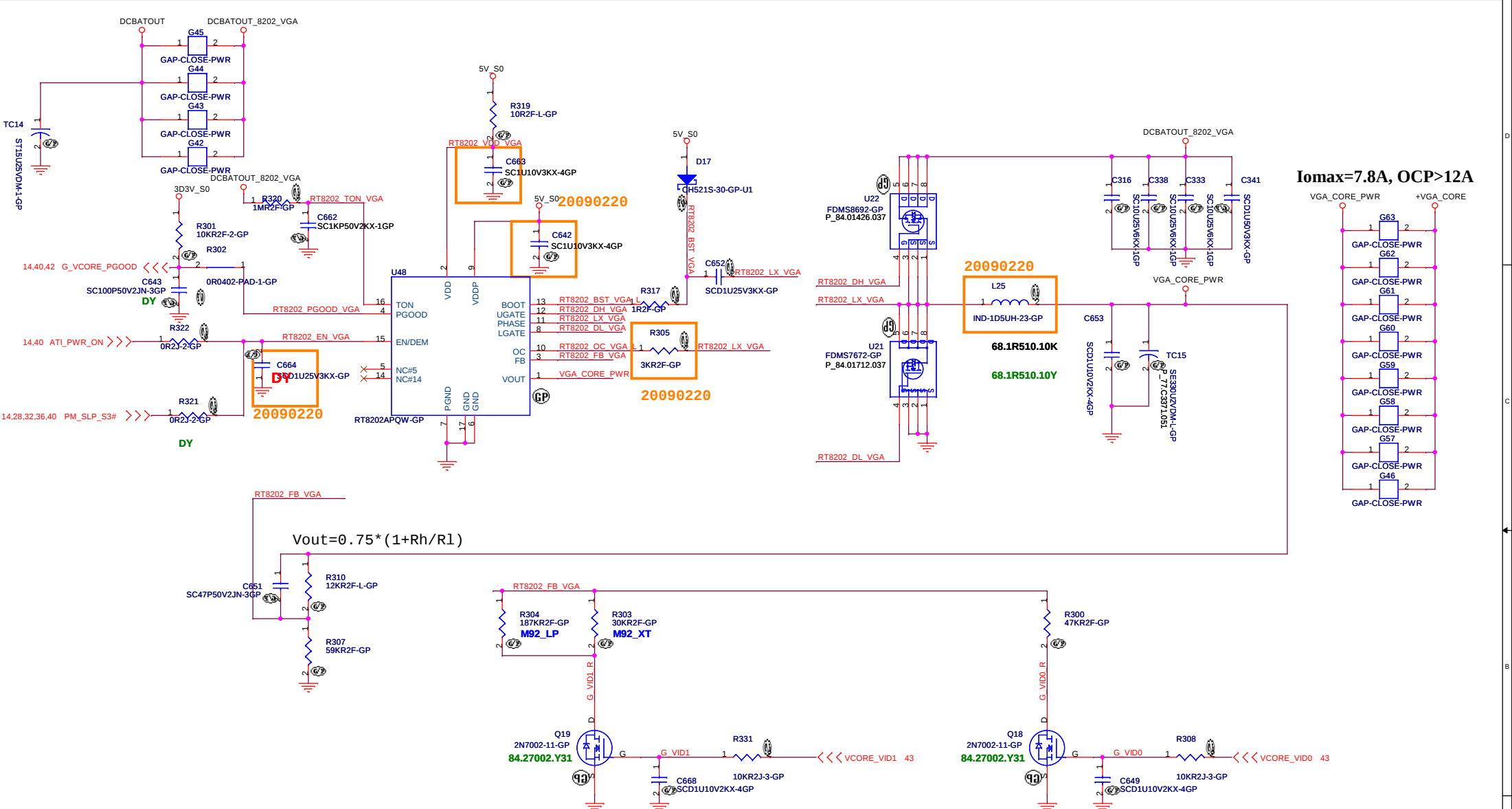
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		RT8202 1D05V	
Size	Document Number	Rev	
A3		JM41 Discrete	
Date: Tuesday, April 28, 2009		Sheet 36	of 48



DIS

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
RT9026 0D75V			
Size	Document Number	Rev	
A3	JM41 Discrete	-2	
Date:	Tuesday, April 28, 2009	Sheet	37 of 48

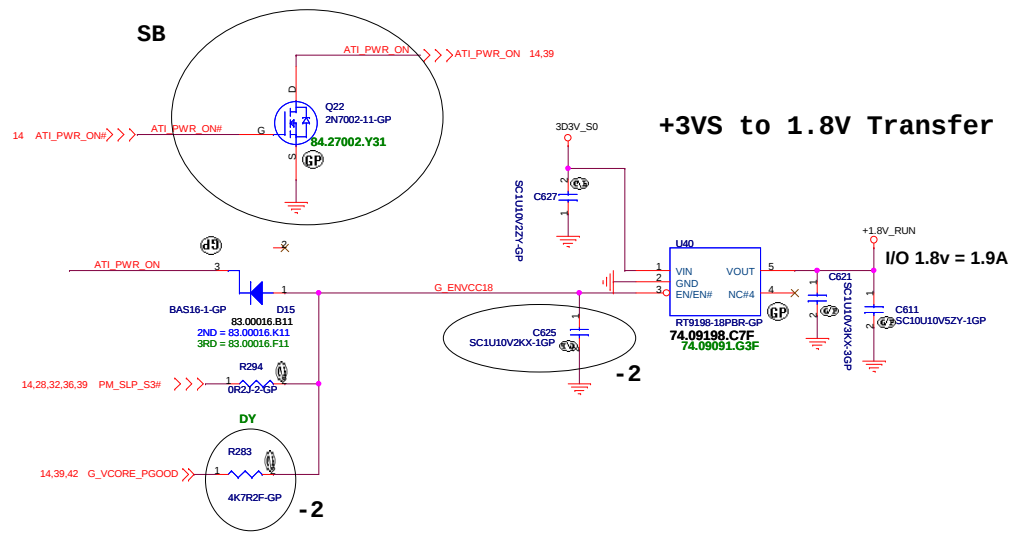


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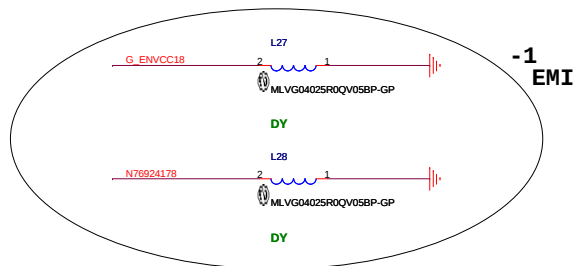
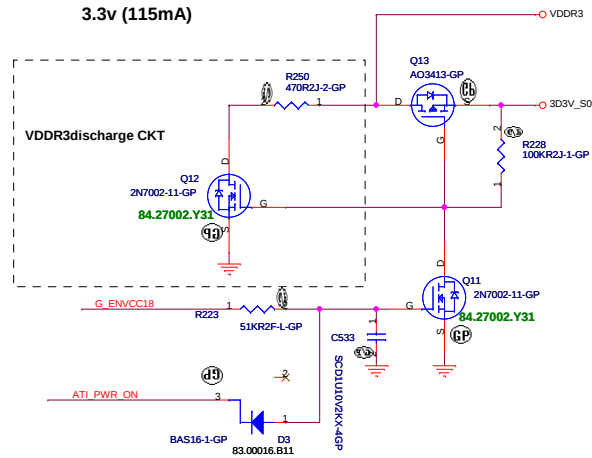
$$V_{out} = 0.75 * (1 + R_h/R_1)$$

M92_LP core power		
ALTV1	ALTV0	Vout
0	0	0.90V
0	1	1.09V
1	0	0.95V

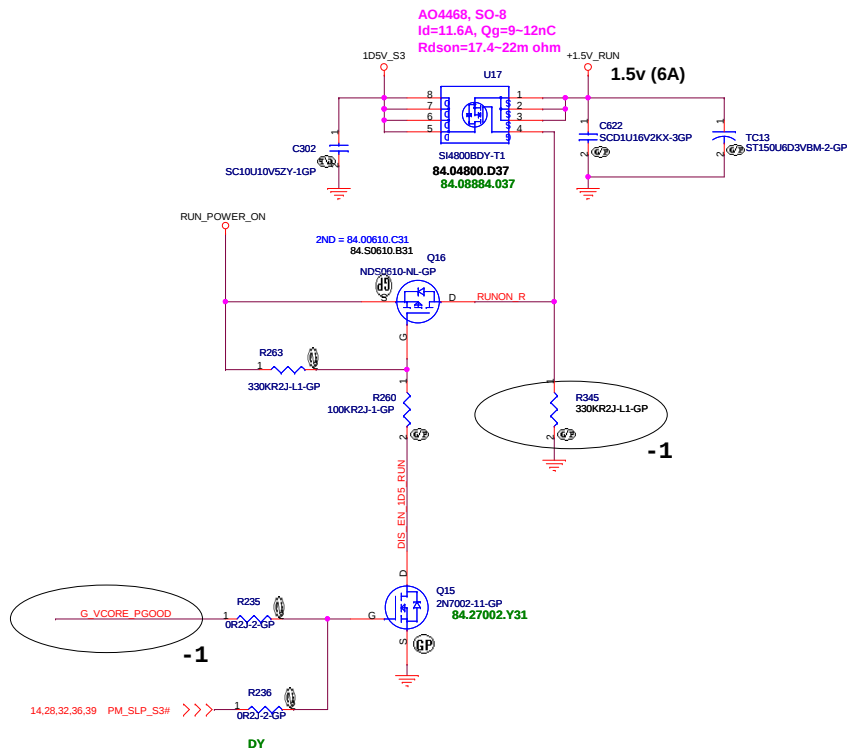
M92_XT core power		
ALTV1	ALTV0	Vout
0	0	0.90V
0	1	1.09V
1	0	1.2V



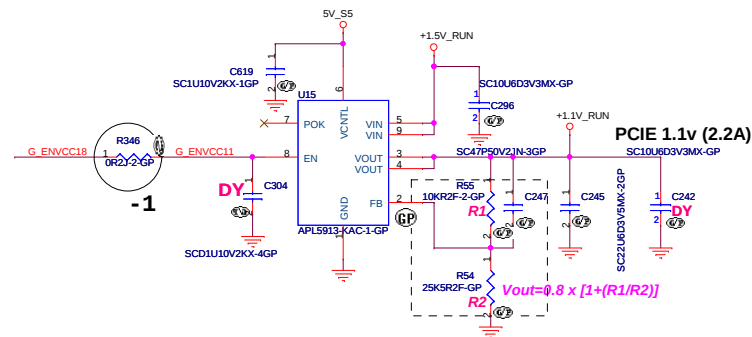
+3VS to 3.3V_DELAY Transfer 3.3v (115mA)



+1.5V to +1.5VS_RUN Transfer

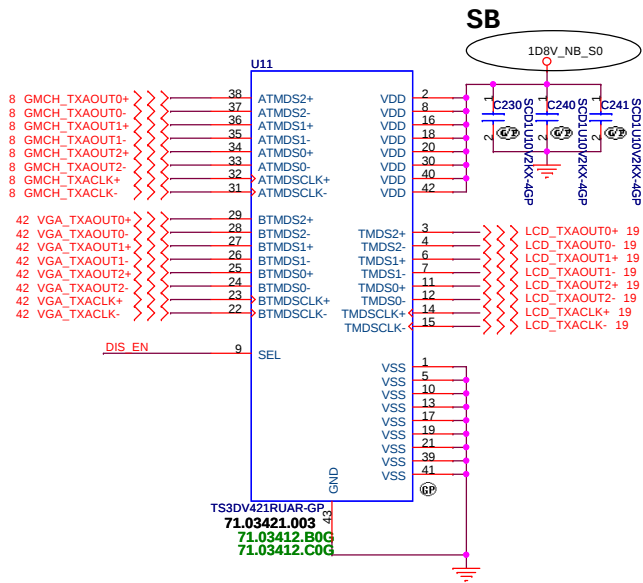


+1.5v to PCIE 1.1V Transfer



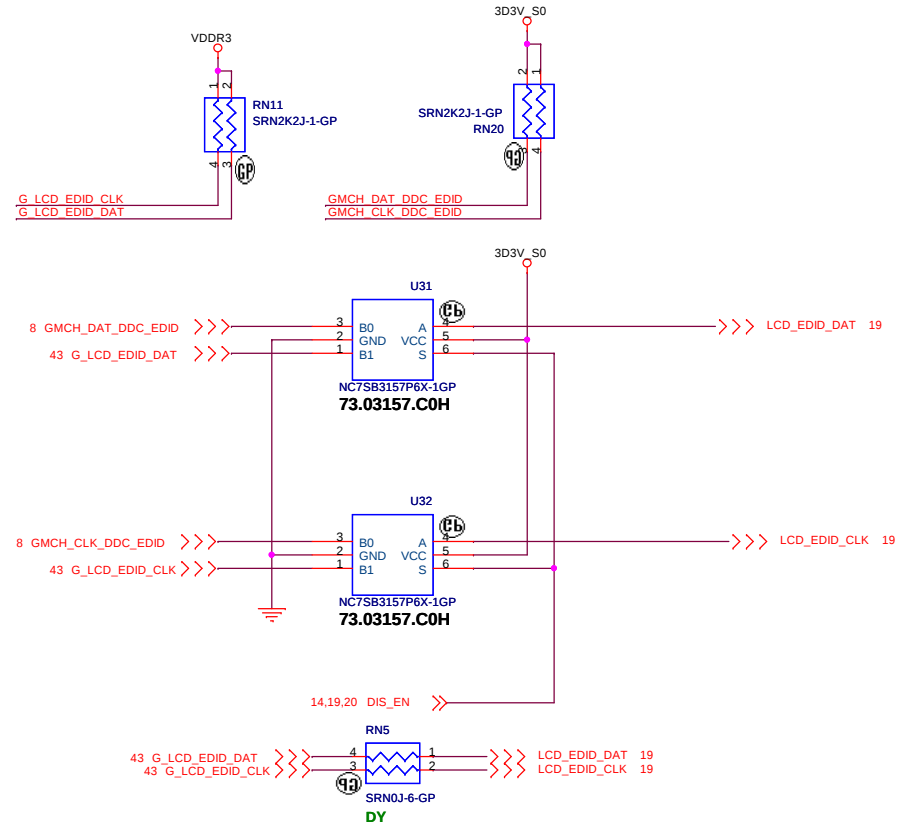
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緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
M92S2 power			
Size Custom	Document Number	JM41 Discrete	Rev -2
Date: Thursday, April 30, 2009	Sheet 40	of 48	

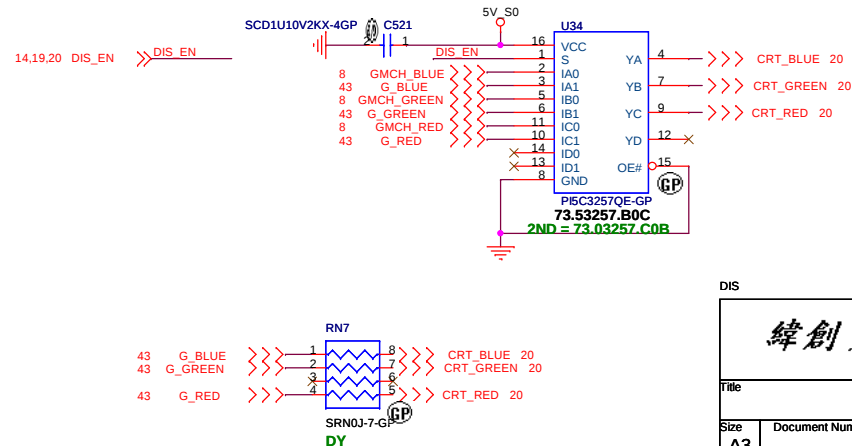
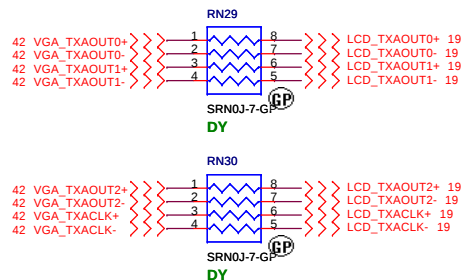


FUNCTION TABLE

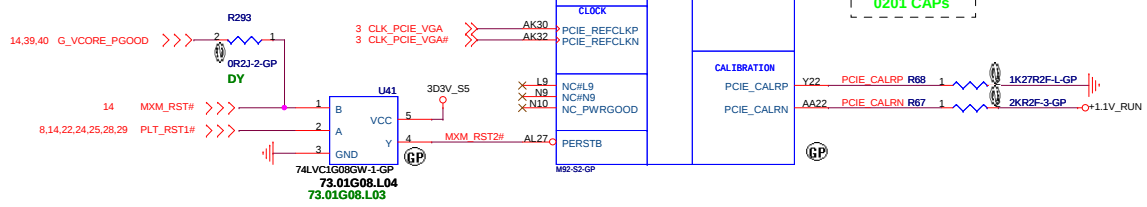
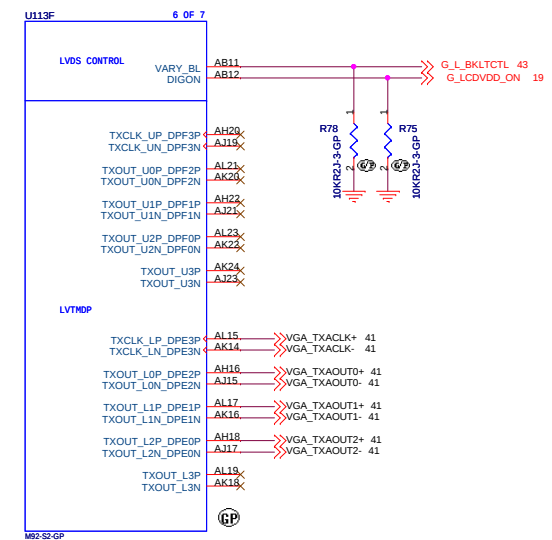
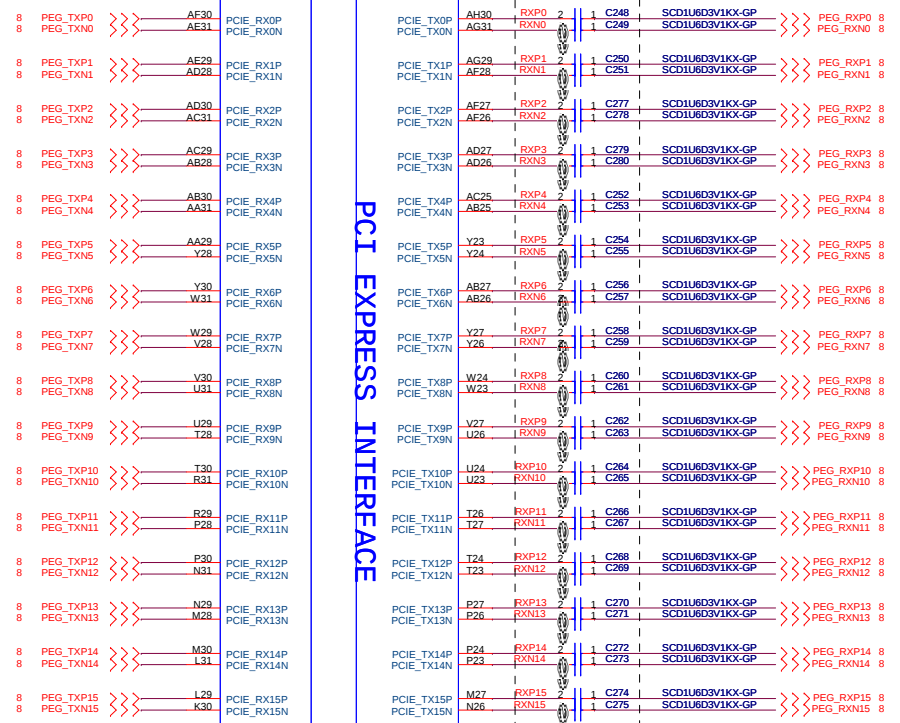
SEL	FUNCTION	OUTPUT
L	TMDSn+ = ATMDSn+ TMDSn- = ATMDSn- TMDSCLK+ = ATMDSCLK+ TMDSCLK- = ATMDSCLK- BTMDSn+ = High Impedance BTMDSn- = High Impedance BTMDSCLK+ = High Impedance BTMDSCLK- = High Impedance	TMDSn+ TMDSn- TMDSCLK+ TMDSCLK-
H	TMDSn+ = BTMDSn+ TMDSn- = BTMDSn- TMDSCLK+ = BTMDSCLK+ TMDSCLK- = BTMDSCLK- ATMDSn+ = High Impedance ATMDSn- = High Impedance ATMDSCLK+ = High Impedance ATMDSCLK- = High Impedance	TMDSn+ TMDSn- TMDSCLK+ TMDSCLK-



$\bar{E}$	S	YA	YB	YC	YD	Function
H	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Disable
L	L	IA0	IB0	IC0	ID0	S = 0
L	H	IA1	IB1	IC1	ID1	S = 1

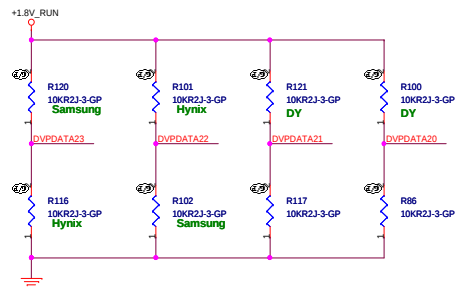


SSID = VIDEO

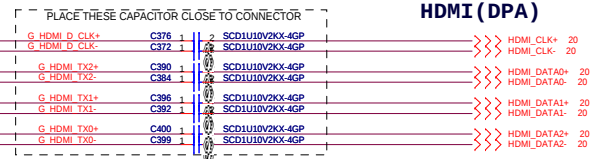
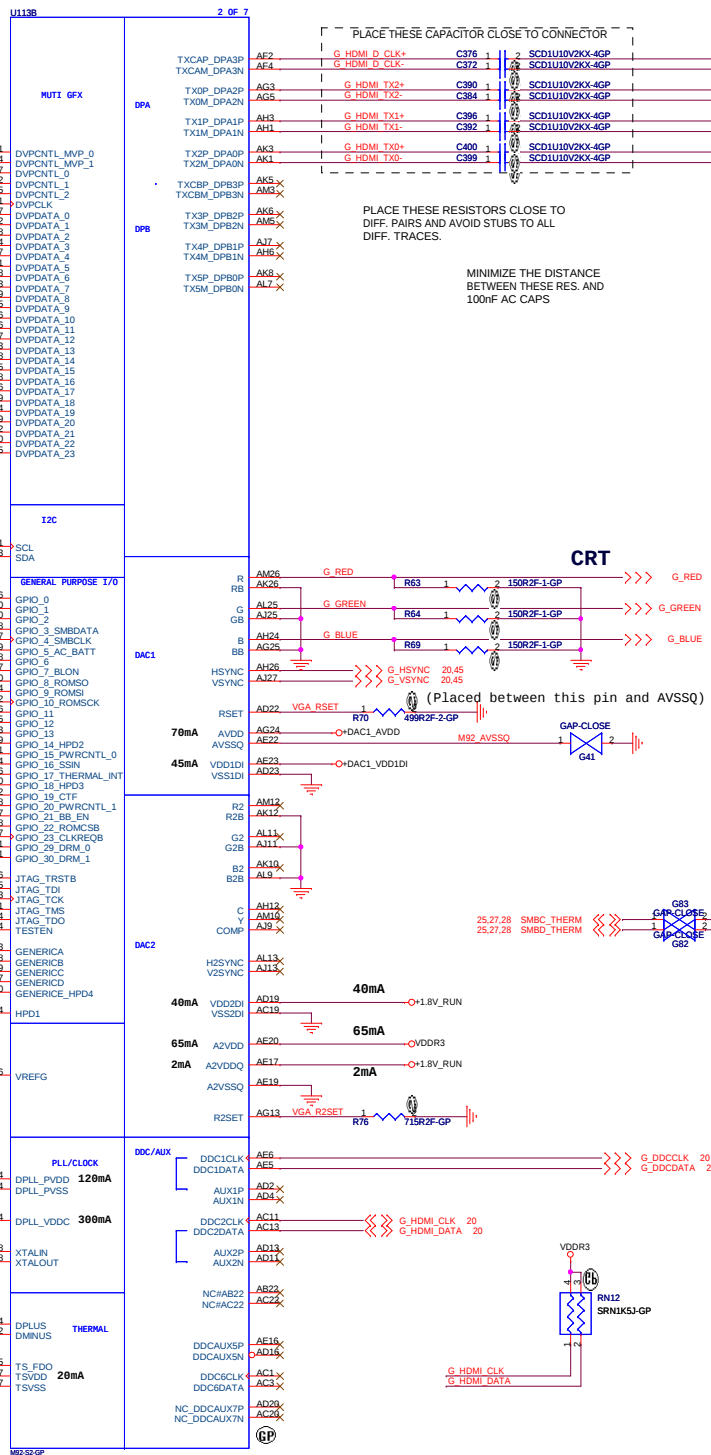
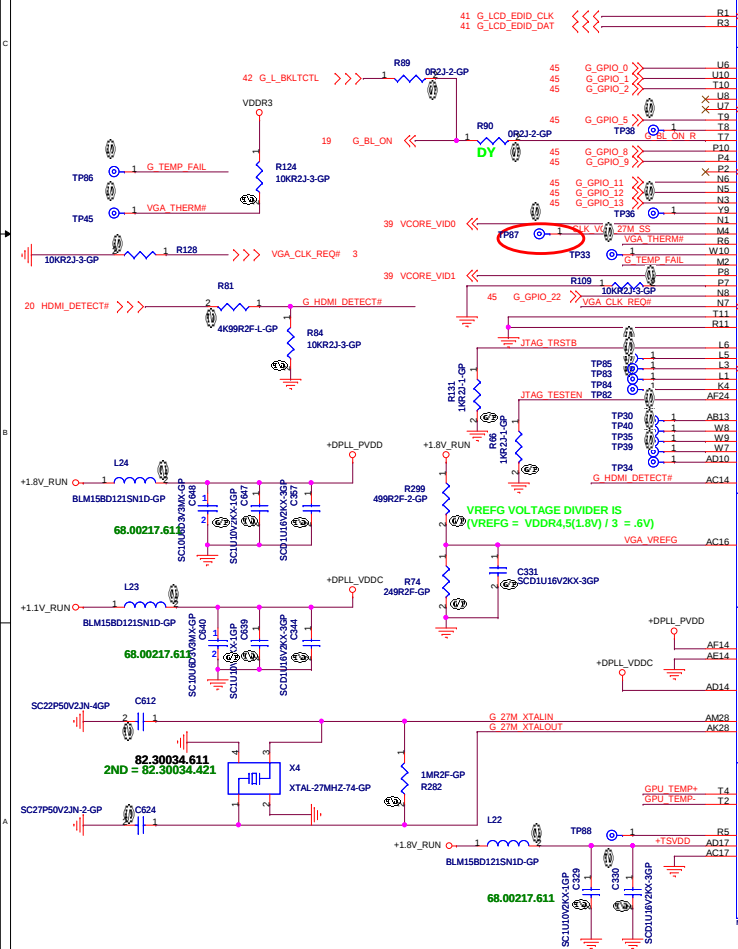


SSID = VIDEO

```
DVPDATA [3:0]
0100 64Mx16 Hynix
1000 64Mx16 Samsung
```

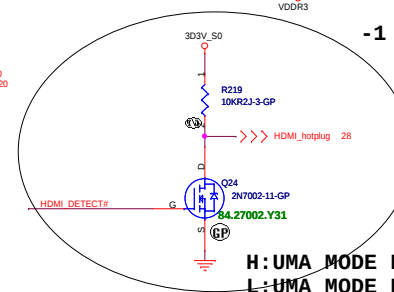
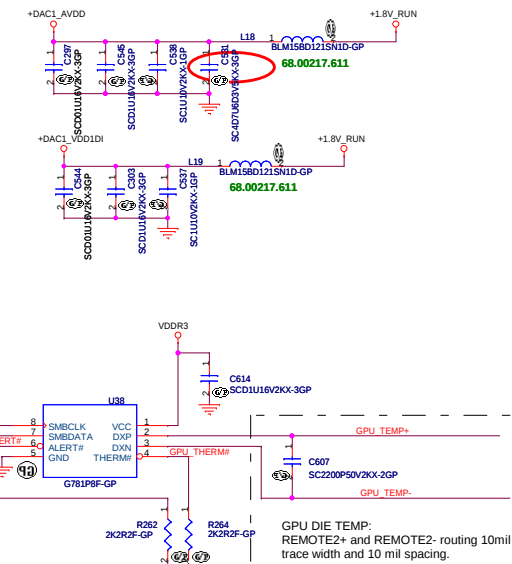


STRAPS	PIN	DESCRIPTION
MEM_TYPE	DVPDATA(23:20) (Internal PD)	MEMORY TYPE, MAKE AND SIZE INFO
		0000 - GDDR3 16Mx32 Qimonda
		0001 - GDDR3 32Mx32 Hynix
		0010 - GDDR3 32Mx32 Qimonda
		0011 - GDDR3 32Mx32 Samsung



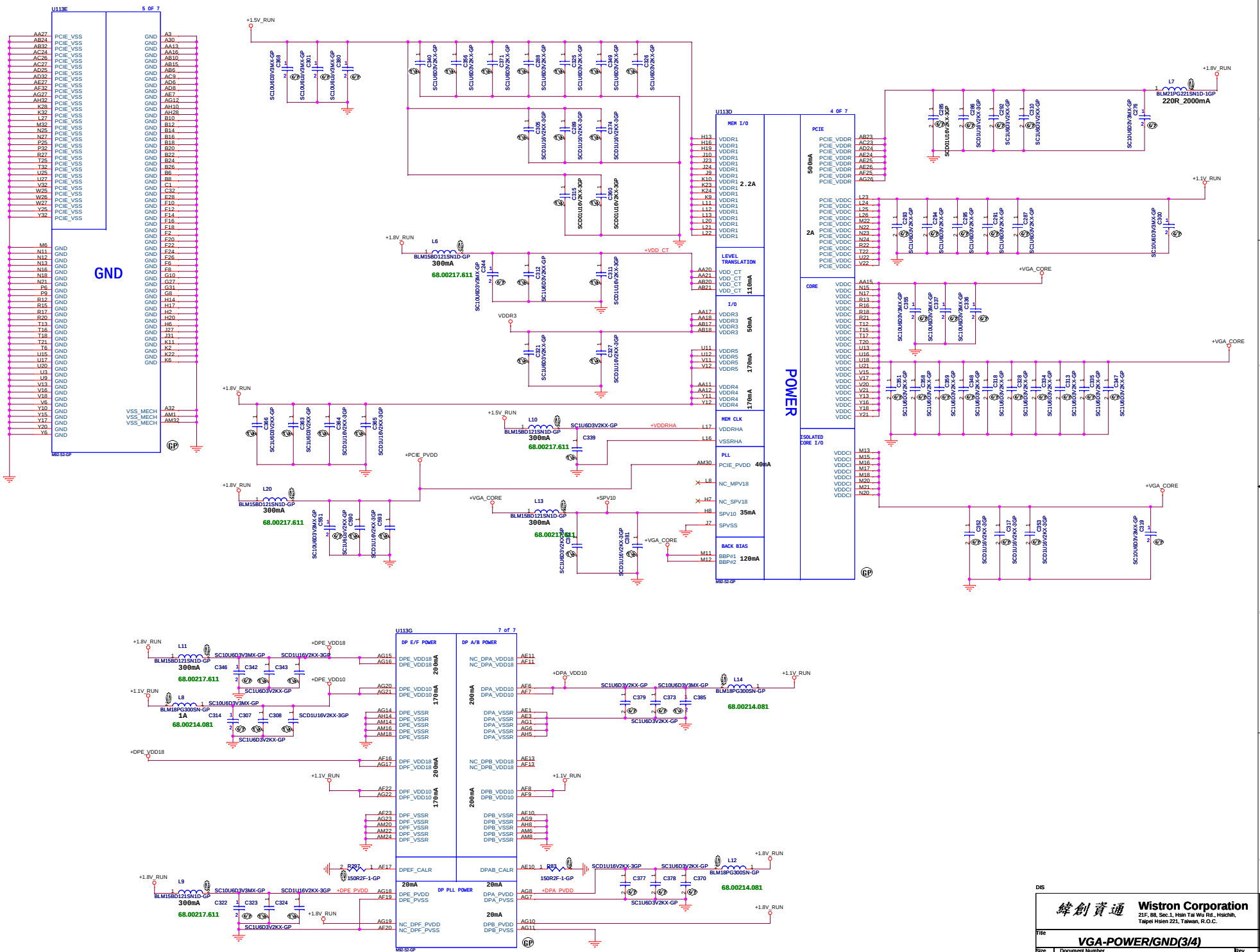
PLACE THESE RESISTORS CLOSE TO
DIFF. PAIRS AND AVOID STUBS TO ALL
DIFF. TRACES.

MINIMIZE THE DISTANCE
BETWEEN THESE RES. AND
100nF AC CAPS



```
H:UMA MODE HDMI PLUG_OUT
L:UMA MODE HDMI PLUG_IN
```

SSID = VIDEO

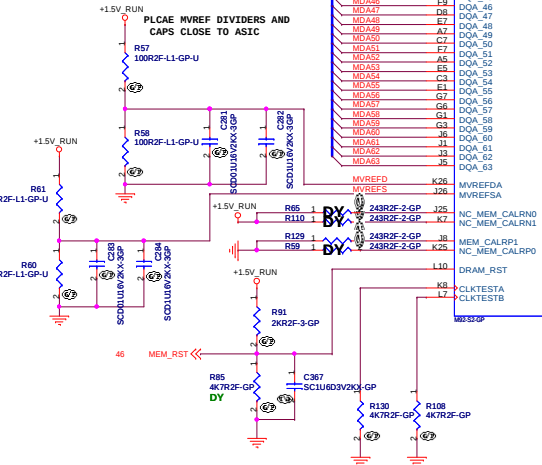


SSID = VIDEO

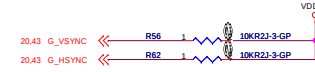
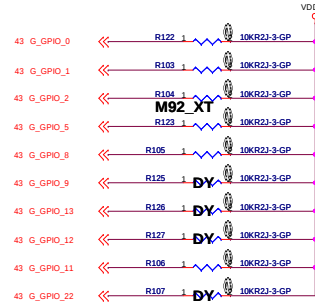
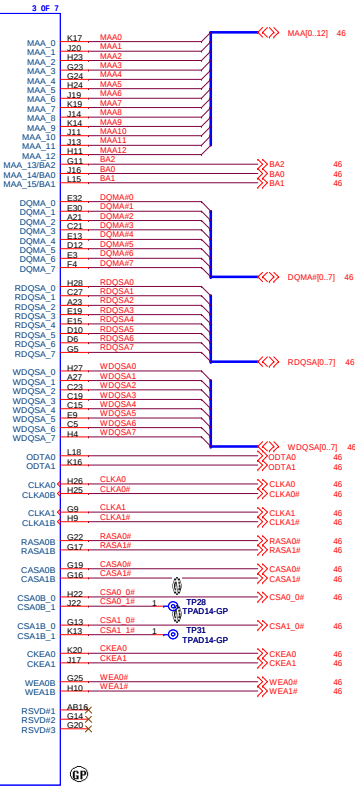
MVDDQ=1.5V FOR DDR3 MEMORY

DIVIDER RESISTORS	DDR2/DDR3	GDDR3
MVREF TO 1.8V	100R	40.2R
MVREF TO GND	100R	100R

PLCAE MVREF DIVIDERS AND CAPS CLOSE TO ASIC



MEMORY INTERFACE

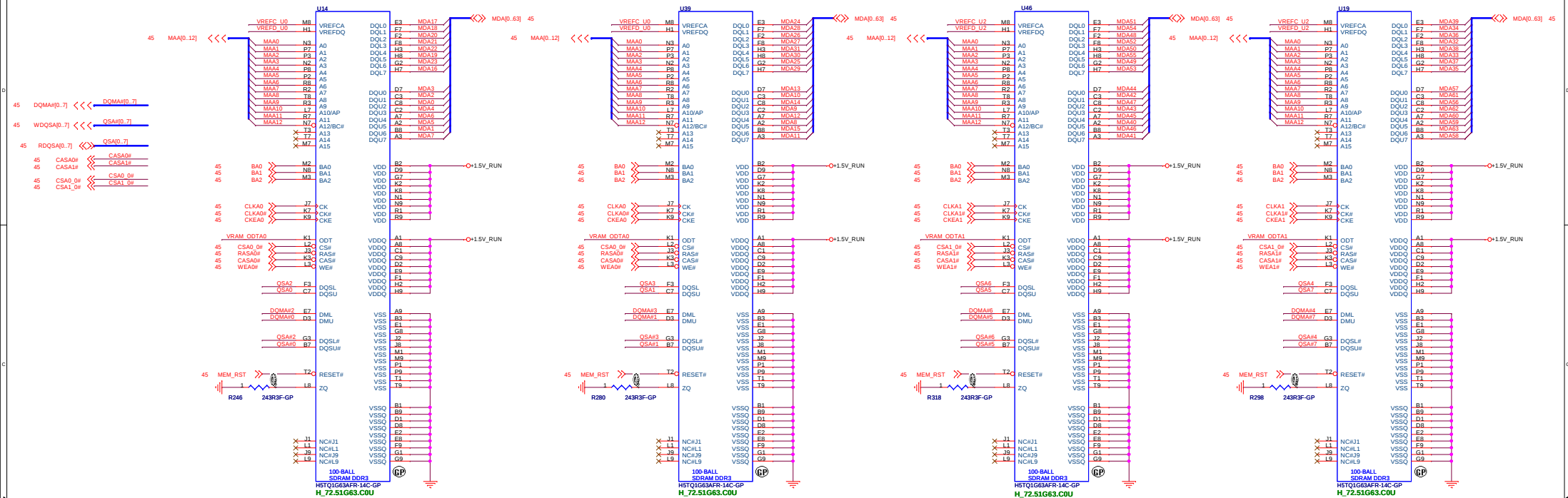


ATI RESERVED CONFIGURATION STRAPS			
ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESE			
GPIO3, H2SYNC, V2SYNC			
PULLUP PADS ARE NOT REQUIRED FOR THESE STRAPS BUT IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET			

If BIOS_ROM_EN (GPIO22) = 0		If BIOS_ROM_EN (GPIO22) = 1		
Size of the primary memory apertures	GPIO[9,13,12,11]	Manufacturer	Part Number	GPIO[13,12,11]
V	128MB	ST Microelectronics	M25P05A	0100
	256MB		M25P18A	0101
	64MB		M25P20	0101
	32MB		M25P40	0101
	512MB	M25P80	0101	
	1GB	Chingis (formerly PMC)	Pm25LV512A	0100
	2GB		Pm25LV810A	0101
	4GB			

STRAPS	PIN	DESCRIPTION
TX_PWRS_ENB (Internal PD)	GPIO0	Transmitter Power Savings Enable 0= 50% Tx output swing 1= Full Tx output swing
TX_DEEMPH_EN (Internal PD)	GPIO1	Transmitter De-emphasis Enable 0= Tx de-emphasis disabled 1= Tx de-emphasis enabled
BIF_GEN2_EN_A	GPIO2	0 = Advertises the PCI-E device as 2.5GT/s 1 = Advertises the PCI-E device as 5GT/s
BIF_CLK_PM_EN	GPIO8	0= Disable CLKREQ# power management capability 1= Enable CLKREQ# power management capability
ROMIDCFG[3:0] (Internal PD)	GPIO[13, 12, 11]	if BIOS_ROM_EN=1, then Config[3:0] defines the ROM type if BIOS_ROM_EN=0, then Config[3:0] defines the primary memory aperture size
BIOS_ROM_EN (Internal PD)	GPIO_22_ROMCSB	Enable external BIOS ROM device 0= Disable external BIOS ROM device 1= Enable external BIOS ROM device
AUD[1] AUD[0] (Internal PD)	VGA_HSYNC VGA_VSYNC	AUD[1:0] 00: No audio function 01: Audio for DisplayPort and HDMI (if adapter is detected) 10: Audio for DisplayPort only 11: Audio for both DisplayPort and HDMI

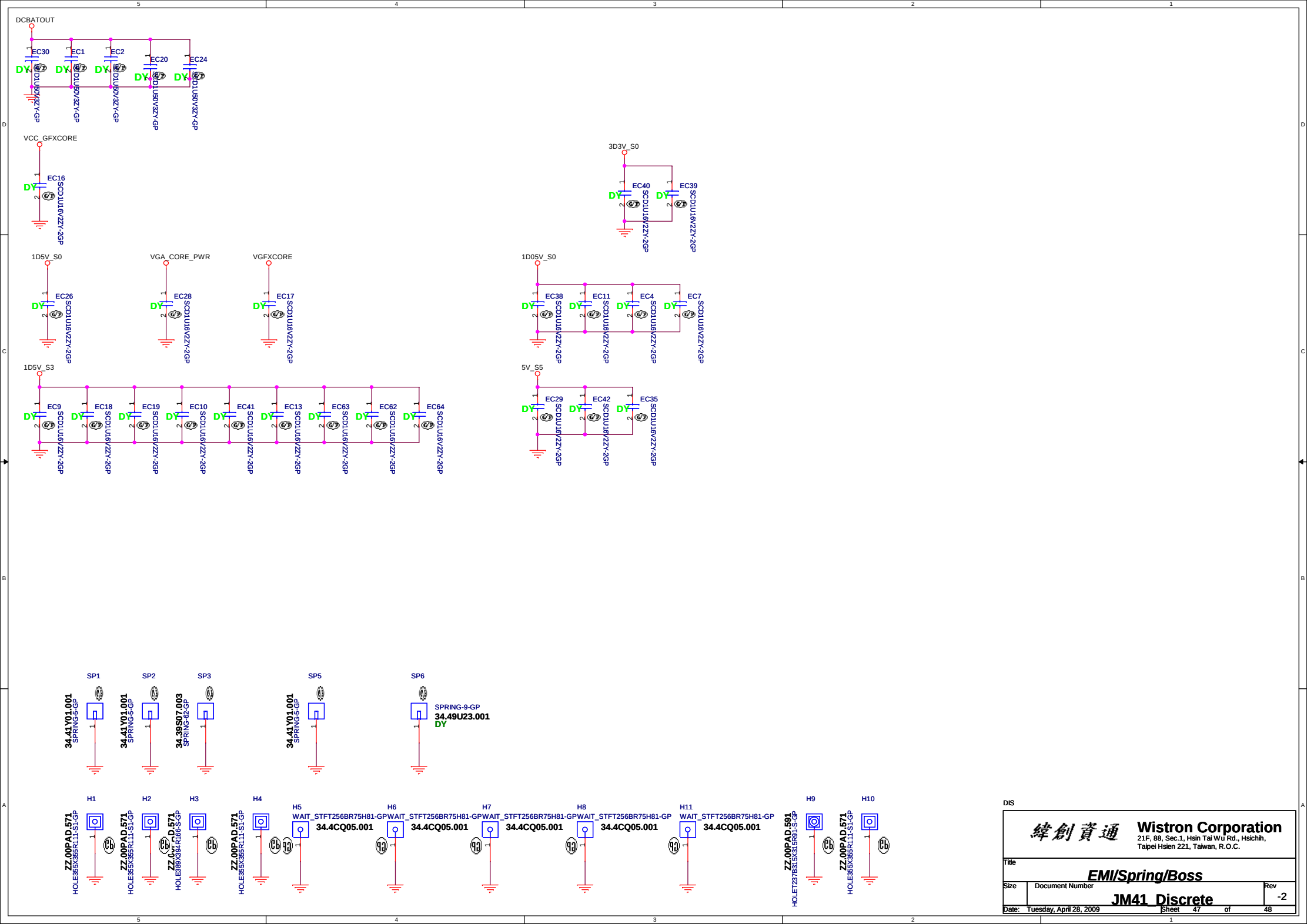
512MB DDR3



Samsung : K4W1G1646E-EC12

Hynix : H5TQ1G63BFR-12C





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Size		Document Number	
Date: Tuesday, April 28, 2009		Sheet 47 of 48	
Rev		-2	

EMI/Spring/Boss

JM41 Discrete

JM41/JM51 DIS Schematic EC Tracking Record

EC #/ Page / Description / Part Affected

EC SC01/11/connect NB1.A31 to GND(For power save)
EC SC02/14/net DIS_EN pull high 10K to 3D3V_S0
EC SC03/20/CN2.pin35 change to AGND
EC SC04/22/R311 change to 39.2K
EC SC05/22/U24.pin2 change to AGND
EC SC06/26/BTB2.pin9 add stand by led control signal
EC SC07/28/U16.pin66 add stand by led control signal
EC SC08/28/add circuit to support green adapter
EC SC09/28/net EJECT_BTN pull high 10K to 3D3V_S0
EC SC10/31/add circuit to stand by led control
EC SC11/40/change GPU power enable signal to ATI_PWR_ON#(low active)
EC SC12/41/change U11 power plane to 1D8V_NB_S0

DIS

緯創資通

Wistron Corporation

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Document Number
JM41_Discrete

Rev
-2

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